

Service Manual

74CD11/00G/01G

Compact disc player



CONTENTS

SECTION	PAGE
1 TECHNICAL SPECIFICATIONS (DIN)	1
2 NOTES ON BALANCED OUTPUTS CONECTORS	2
3 BLOCK DIAGRAM	3
4 SCHEMATIC DIAGRAM AND PARTS LOCATION (PATTERN SIDE)	5
5 CONNECTION DIAGRAM	29
6 EXPLODED VIEW AND PARTS LIST	31
7 TRAY MECHANISM LOADING PROCEDURES	37
8 PRACTICAL HINTS	39
9 MEASUREMENTS AND ADJUSTMENTS	40
10 ELECTRICAL PARTS LIST	51

marantz®

model CD11

First issue : 1990

4822 725 50915

MZ 2512

MARANTZ DESIGN AND SERVICE

Using superior design and selected high grade components, MARANTZ company has created the ultimate in stereo sound.

Only **original MARANTZ parts** can insure that your MARANTZ product will continue to perform to the specifications for which it is famous.

Parts for your MARANTZ equipment are generally available to our National Marantz Subsidiary or Agent.

ORDERING PARTS:

Parts can be ordered either by mail or by telex. In both cases, correct part number has to be specified. The following information must be supplied to eliminate delays in processing your order:

1. Complete address
2. Complete part numbers and quantities required
3. Description of parts
4. Model number for which part is required
5. Way of shipment
6. Signature: any order form or telex must be signed otherwise such part order will be considered as null and void.

PARTS ORDERING

Parts may be ordered at the following addresses:

AUSTRIA
HORNYPHON
Vertriebsgesellschaft GmbH
Wienerbergstrasse 1
A 1101 Wien
Austria
Telex: 132.332

BELGIUM
SVD DIVISION MARANTZ
Industrialaan 1
1720 Groot-Bijgaarden
Belgium
Telex: 24466

CHILE
MARANTZ
DIVISION OF PHILIPS S.A.
AV. Santa Maria, 0760
Casilla 2687
Santiago
Telex: 240.239

DENMARK
MARANTZ
DIVISION OF PHILIPS
SERVICE A/S
Prags Boulevard 80
Postbox 1919
DK-2300 København S
Denmark
Telex: 31201

FINLAND
MARANTZ
DIVISION OF OY PHILIPS Ab
Kaivokatu 8
00100 Helsinki
Finland
Telex: 124811

FRANCE
MARANTZ FRANCE
4 Rue Bernard Palissy
92600 Asnières
France
Telex: 611651

GERMANY
MARANTZ GERMANY GmbH
Alexanderstrasse 1
2000 Hamburg
Germany

THE NETHERLANDS
Elpro Marantz
Wint Hontlaan 28
3526 KV Utrecht
The Netherlands
Telex: 4748

NORWAY
MARANTZ
DIVISION OF PHILIPS A/S
Sandstuveien 40
0680 Oslo 6
Norway
Telex: 72640

GREAT BRITAIN
MARANTZ AUDIO U.K. Ltd
Unit 15/16
Saxon Way Industrial Estate
Moor Lane
Harmondsworth UB7 OLV
Great Britain
Telex: 935196

GREECE
SHERTON ELECTRONICS S.A.
P.O.Box 21025
Hippocrates Street 188
Athens 11471
Greece
Telex: 216.795

JAPAN
MARANTZ JAPAN, Inc.
35-1, 7-chome, Sagamiono
Sagamihara-shi, Kanagawa
Japan

KUWAIT
AL ALAMIAH ELECTRONICS
Ussama Building
Fahd al Saleem Street
P.O.Box 23781
Safat-Kuwait
Telex: 22694

ITALY
MARANTZ ITALIANA S.P.A.
Via Chiese, 74
20126 Milano
Italy

SAUDI ARABIA
AL ALAMIAH ELECTRONICS
P.O.Box 5954
University Street
Riyadh 11432
Saudi Arabia
Telex: 401530

SOUTH AFRICA
MARANTZ
DIVISION OF PHILIPS S.A.
Main Road Martindale
P.O. Box. 58088
Newville 21114
South Africa

SPAIN
PHONO S.A.
Ignacio Iglesias 10
Badalona (Barcelona)
Spain
Telex: 59355

SWEDEN
MARANTZ
DIVISION OF PHILIPS
Försäljning AB
Tegeluddsvägen 1
S-115 84 Stockholm
Sweden
Telex: 14060

SWITZERLAND
MARANTZ
Technischer Service
Duenstrasse 3
3186 Düringen
Switzerland

TURKEY
DOGRUOL Ltd.
I.M.C.
6 Blok N°6310
Unkapani
Istanbul
Turkey
Telex: 22085

MALTA
CACHIA & GALEA
Republic Street, 68D
Valetta
Telex: 1682

PORTUGAL
MARANTZ
Divisao philips S.A. service
Outurela-carnaxide
2795 LinDA-A-VELHA
Telex: 43906

All of the above locations are fully equipped to take care of your total service needs. Because various countries have differing configuration requirements, it is necessary that you contact the service facility in your particular country. In the event that there is no service location listed for your country, please, contact the nearest facility for the necessary assistance.

In case of difficulties, do not hesitate to contact the Technical Department at abovementioned address.

1. TECHNICAL SPECIFICATIONS (DIN)

Audio Characteristics

Channels	2 channels
D/A conversion	1-bit linear/channel

Frequency Characteristics

Line output jack	20 to 20,000 Hz, \pm 0.2 dB
BALANCED output jack	20 to 20,000 Hz, \pm 0.2 dB
Dynamic range	96 dB
S/N ratio	96 dB
Channel separation	96 dB or more (1 kHz)
THD	0.0025% (1 kHz)
Wow & flutter	Precision of quartz
Analog output jacks	
Line output jacks	Output level 2V RMS
	Output impedance 100 ohms
Matching load impedance	10 kilohms or more
BALANCED output jack	Output level 3V RMS
	Output impedance 100 ohms
Matching load impedance	Balanced 600 ohms
	Unbalanced 600 ohms to 50 kilohms
Digital output	Pin jack, 0.5 V _{p-p} /75 ohms
	(Rectangular optical connector)
	optical output – 19 dBm

Optical Readout System

Laser	AlGaAs semiconductor
Wavelength	780 nm

Signal System

Sampling frequency	44.1 kHz
Quantization	16-bit linear/channel
Error correction	Cross-interleave read solomon code (CIRC), Class A D/A conversion

Power Supply

Power Requirements	E version	110V/120V/220V/24V AC, 50Hz/60Hz
	W version	220 V/240V AC, 50Hz/60Hz
	U version	120V AC, 50 Hz/60 Hz
Power Consumption		17 W

Cabinet, etc.

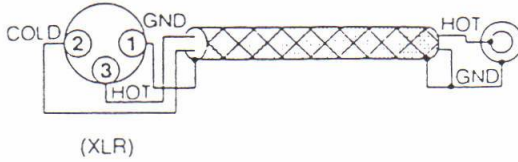
Max. dimensions	
Width	457 mm
Height	140 mm
Depth	359 mm
Dimensions	
Width	454 mm
Height	122 mm
Depth	342 mm
Weight	Approx. 16.7 kg
Operating temperatures	+ 5 to + 35 °C
Operating humidity	5% to 65% (without condensation)

2. NOTES ON BALANCED OUTPUTS CONNECTORS

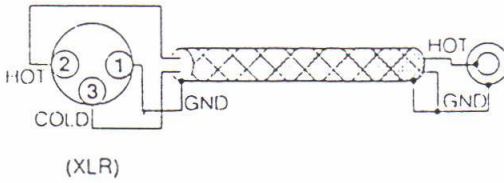
The BALANCED output connectors uses XLR connectors.

There are two types of professional-type internal wiring methods for XLR connectors.

1. USA method (Pin 2 = COLD, Pin 3 = HOT)



2. Europe method (Pin 2 = HOT, Pin 3 = COLD)

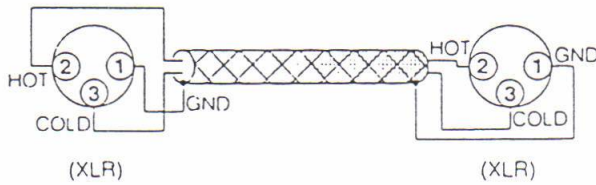


The models use the USA method described in 1 above.

When XLR connector cables are used and if your preamplifier or main amplifier uses the Europe method, the reproduced signal may be out of phase.

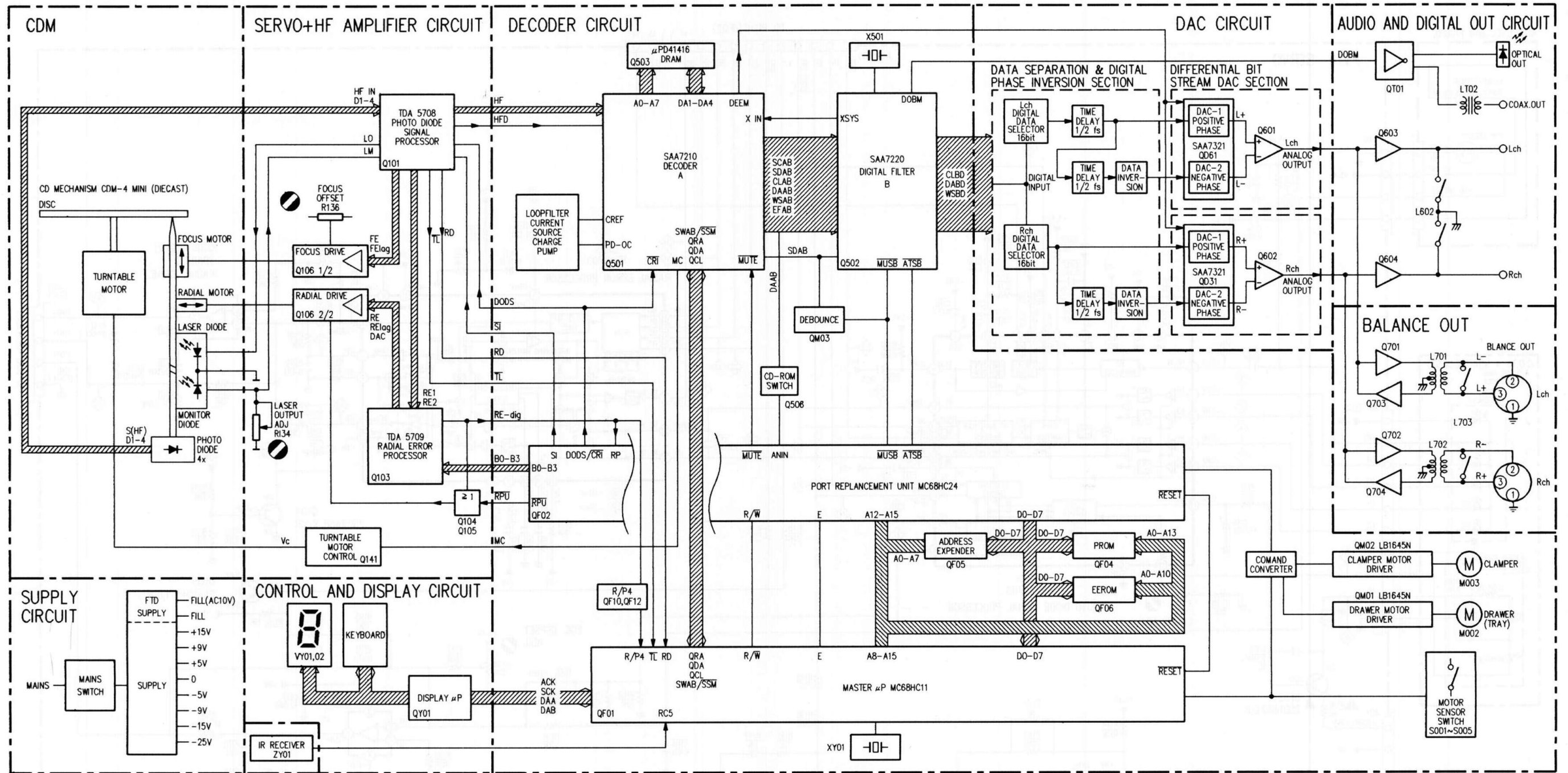
In this case, change the connections of pin 2 and pin 3 of one of the XLR connectors of the cable to the USA method.

Also when you use an XLR balanced cable (see illustration below) and if the preamplifier or main amplifier uses the Europe method, change the connections of pin 2 and pin 3 of one of the XLR connectors of the cable to the USA method.



Now the signal can be reproduced in proper phase.

3. BLOCK DIAGRAM



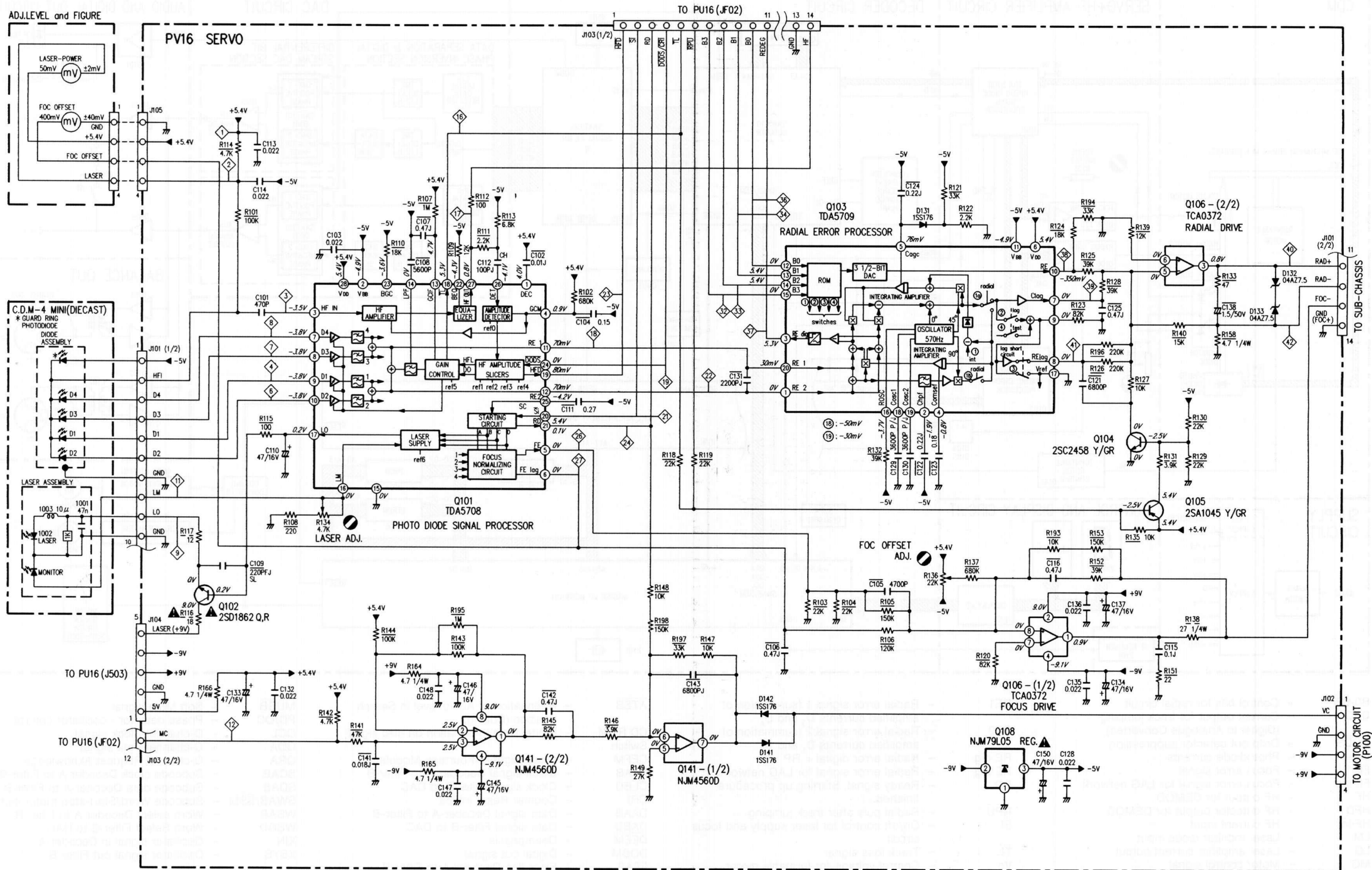
- B0-B3 - Control bits for radial circuit
- DAC - Current output for track jumping (Digital to Analogue Converted)
- DODS - Drop out detector suppression
- D1+4 - Photodiode currents
- FE - Focus error signal
- FE lag - Focus error signal for LAG network
- HF - HF output for DEMOD
- HFD - HF detector output for DEMOD
- HF-in - HF current input
- LM - Laser monitor diode input
- LO - Laser amplifier current output
- MC - Motor control signal
- RE - Radial error signal (Amplified RE₂-RE₁ currents)

- RE1 - Radial error signal 1 (summation of amplified currents D₃ and D₄)
- RE2 - Radial error signal 2 (summation of amplified currents D₁ and D₂)
- RE dig - Radial error digital = RP
- RE lag - Radial error signal for LAG network
- RD - Ready signal, Starting up procedure finished.
- RP - Radial puls after track jumping
- Si - On/off control for laser supply and focus circuit
- TL - Track loss signal
- Vc - Control voltage for turntable motor

- ATSB - Attenuation of Audio level in Search position (Cueing)
- CD ROM Switch - Digital Data information on disc signal
- CEFM - Clock Eight-to-Fourteen Modulator
- CLAB - Clock signal Decoder-A to Filter-B
- CLBD - Clock signal Filter-B to DAC
- CRI - Counter Reset Inhibit
- DAAB - Data signal Decoder-A to Filter-B
- DABD - Data signal Filter-B to DAC
- DEEM - Deemphasis
- DOBm - Digital out signal
- EFAB - Error flag Decoder-A to Filter-B
- CREF - Reference Current
- MUTE - Mute signal

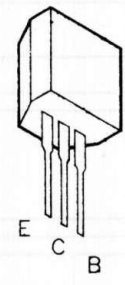
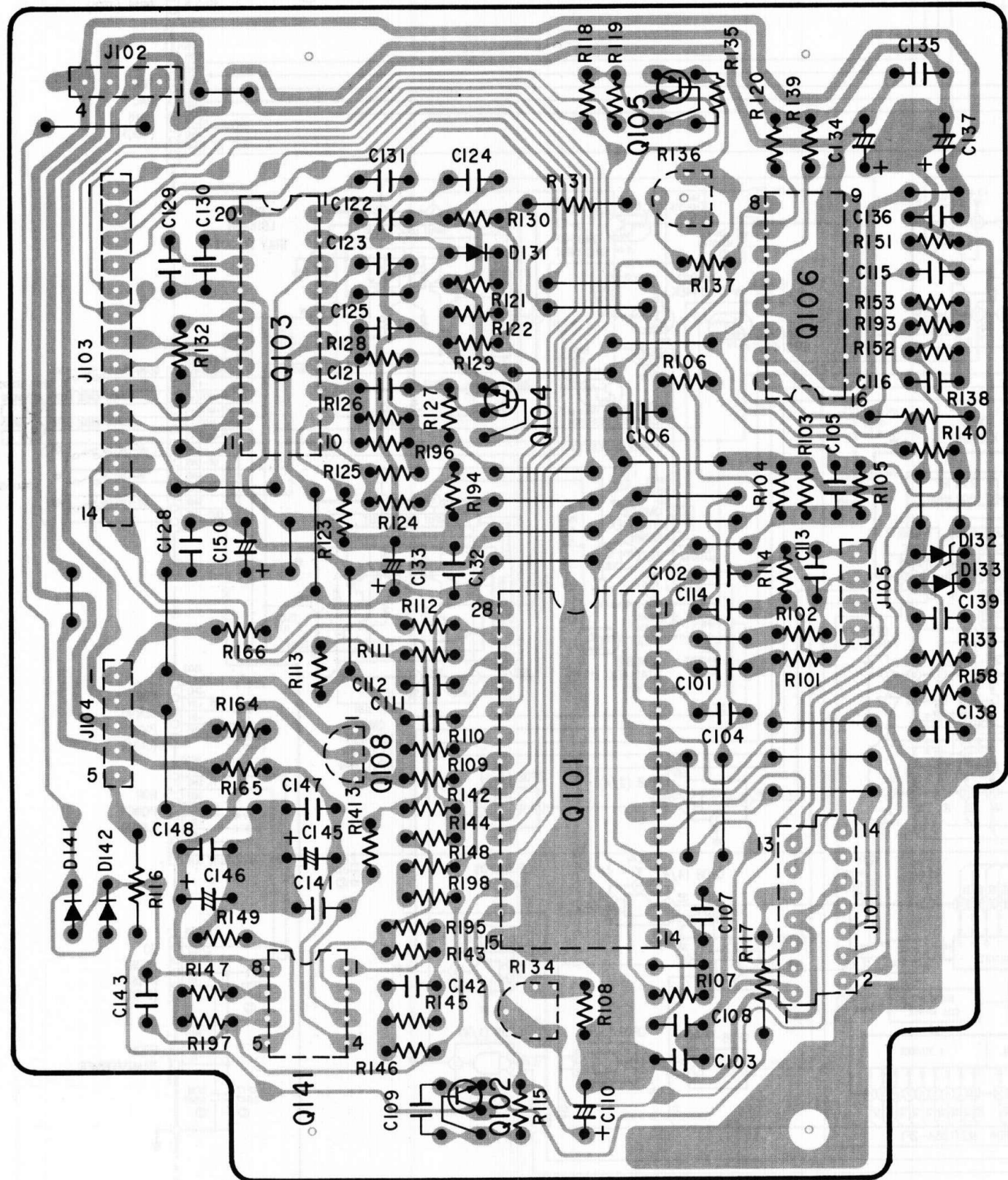
- MUSB - Soft Mute signal
- PD/OC - Phase detector - oscillator control
- QCL - Q-channel Clock signal
- QDA - Q-channel Data signal
- QRA - Q-channel Request Acknowledge
- SCAB - Subcode clock Decoder-A to Filter-B
- SDAB - Subcode data Decoder-A to Filter-B
- SWAB/SSM - Subcode Word/Start-stop motor signal
- WSAB - Word select Decoder-A to Filter-B
- WSBD - Word Select Filter-B to DAC
- XIN - Oscillator signal in Decoder-A
- XSYS - Oscillator signal out Filter-B

4. SCHEMATIC DIAGRAM AND PARTS LOCATION (PATTERN SIDE)

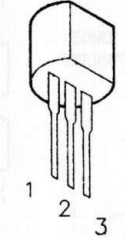


PVI6 SERVO

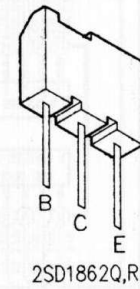
Q103 Q108 Q104 Q105 Q106
Q141 Q102 Q101



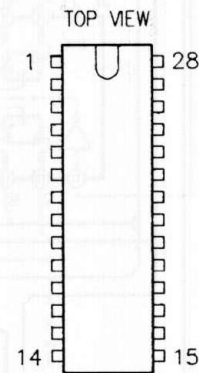
2SA1045 Y/GR
2SC2458 Y/GR



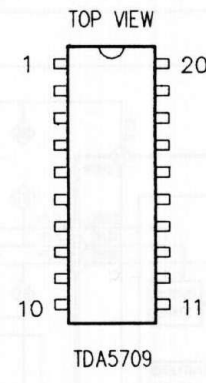
MC79L05



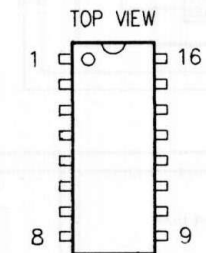
2SD1862Q,R



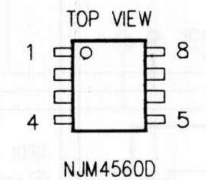
TDA5708



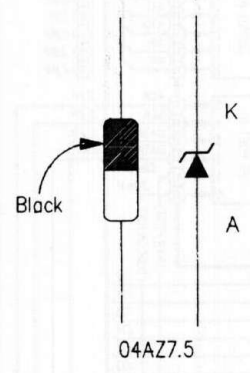
TDA5709



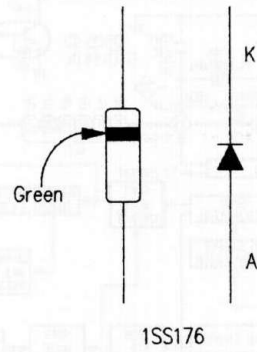
TCA0372



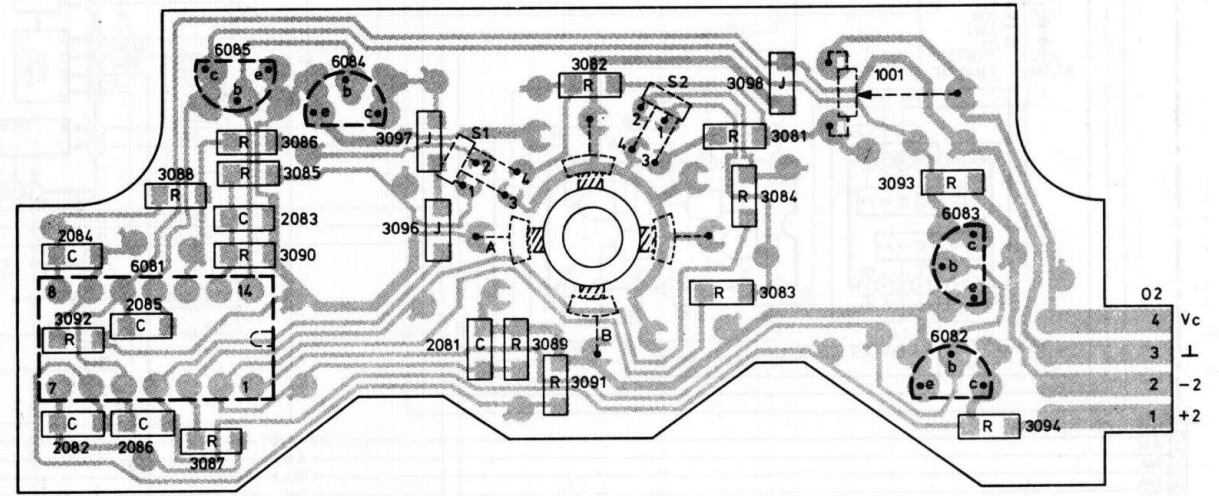
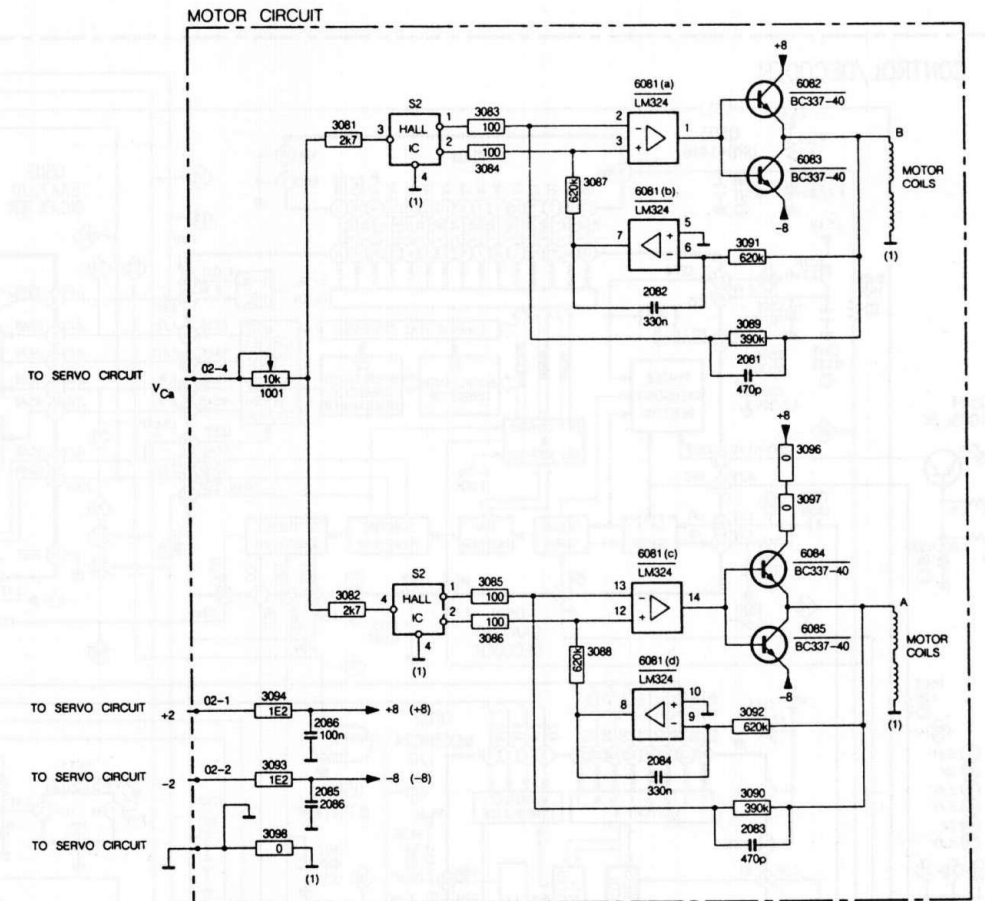
NJM4560D



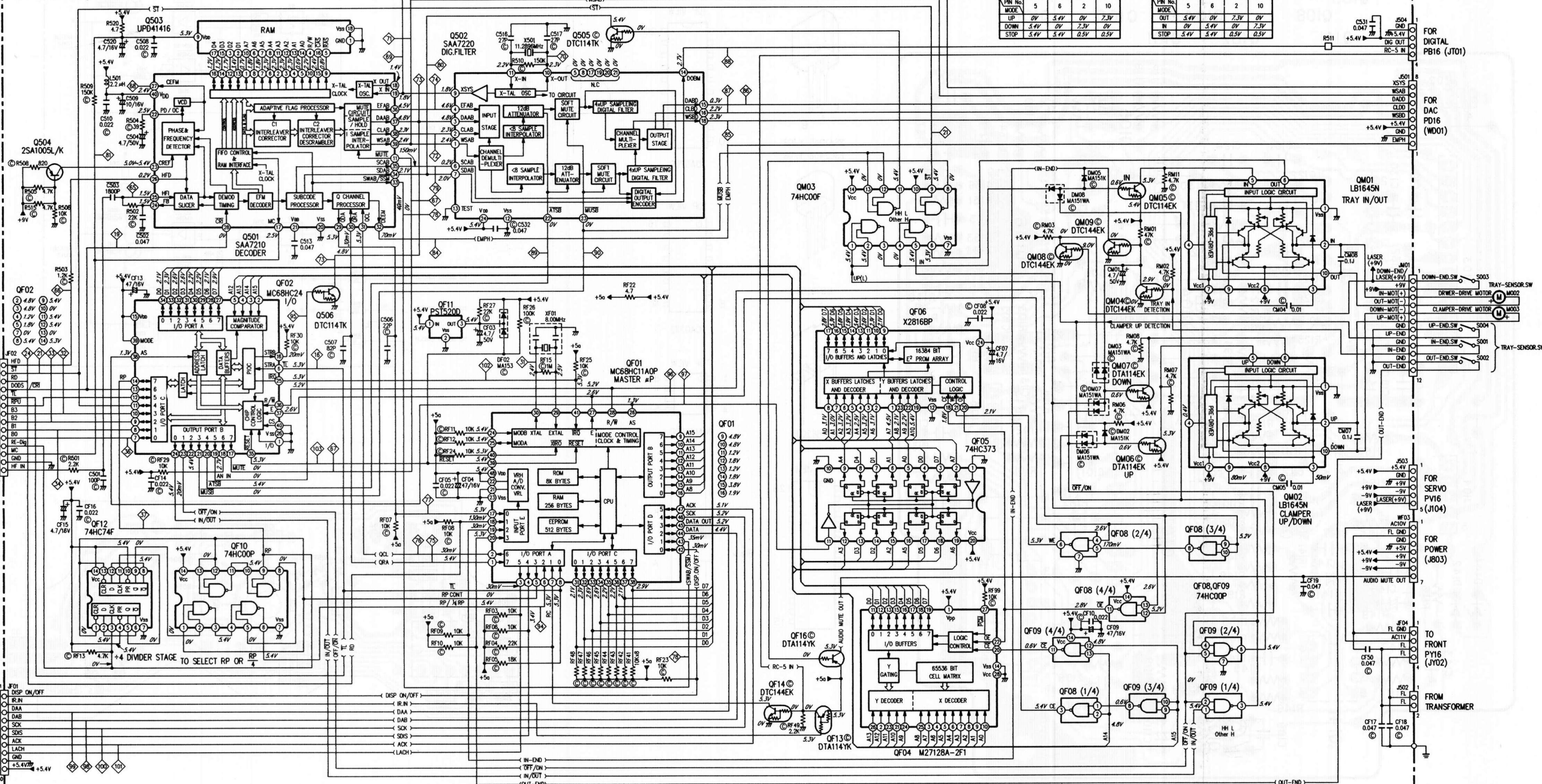
04A27.5



1SS176



PU16 CONTROL/DECODER



QMO2

PN No.	5	6	2	10
UP	0V	5.4V	0V	7.3V
DOWN	5.4V	0V	7.3V	0V
STOP	5.4V	5.4V	0.5V	0.5V

QMO1

PN No.	5	6	2	10
OUT	5.4V	0V	7.3V	0V
IN	0V	5.4V	0V	7.3V
STOP	5.4V	5.4V	0.5V	0.5V

⊙ : CHIP COMPONENT
 □ : CHIP JUMPER (0 0)

FOR SERVO PV16 (J103)

TO FRONT PY16 (JY01)

FOR DIGITAL PB16 (JT01)

FOR DAC PD16 (WD01)

FOR SERVO PV16 (J104)

FOR POWER (J803)

TO FRONT PY16 (JY02)

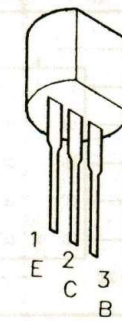
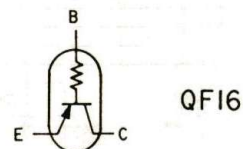
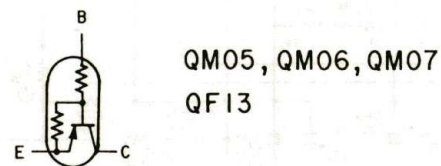
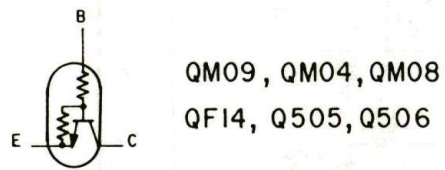
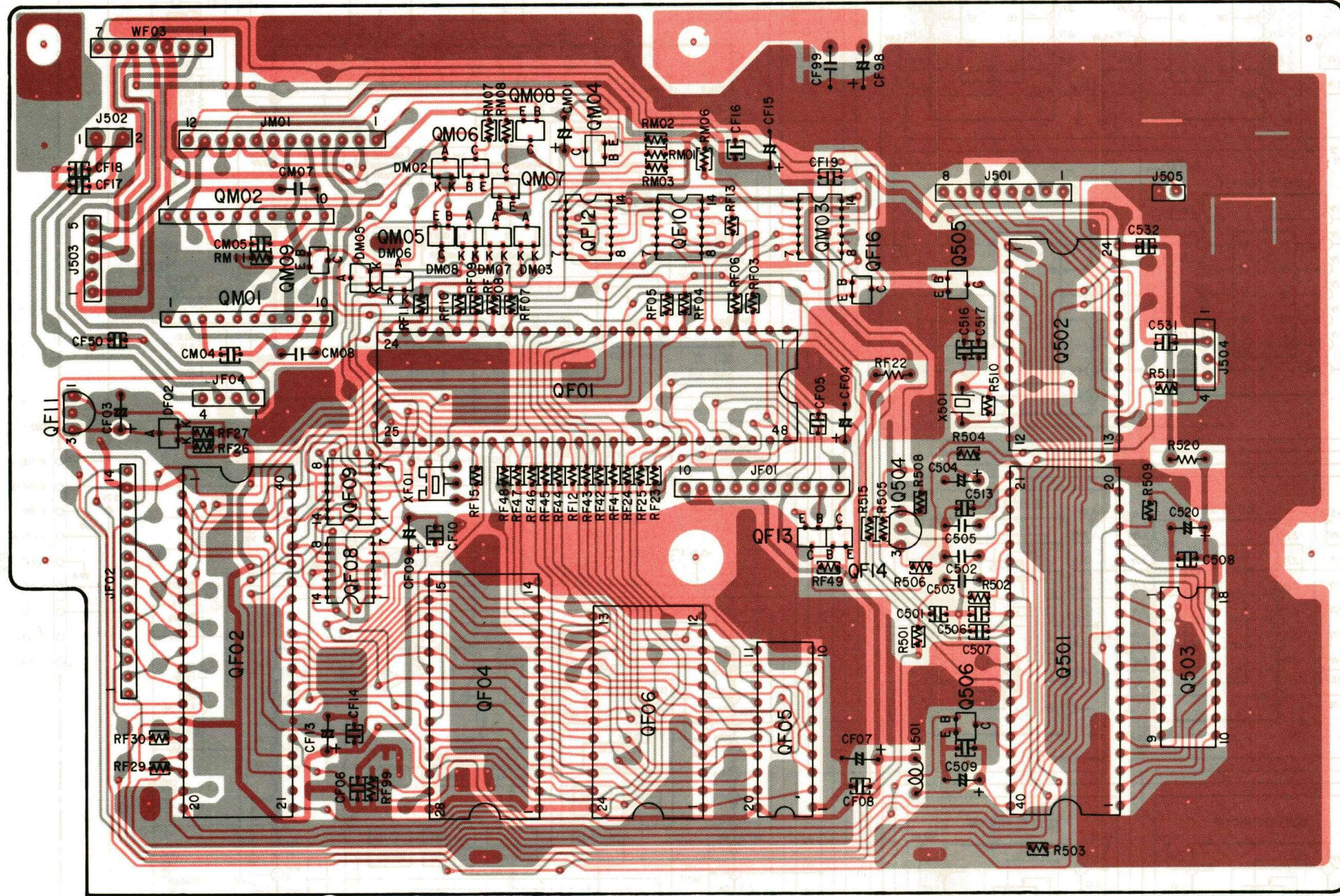
FROM TRANSFORMER

- QF05 ① 5.4V ② 1.8V ③ 2.9V ④ 2.1V ⑤ 1.2V ⑥ 1.0V ⑦ 2.3V ⑧ 2.1V ⑨ 2.5V ⑩ 2.1V ⑪ 2.3V ⑫ 2.6V ⑬ 1.4V ⑭ 2.6V ⑮ 1.2V ⑯ 2.2V ⑰ 2.0V ⑱ 1.9V ⑳ 0.6V ㉑ 1.8V ㉒ 2.8V ㉓ 1.2V ㉔ 3.8V ㉕ 2.0V ㉖ 1.2V ㉗ 5.4V ㉘ 5.4V

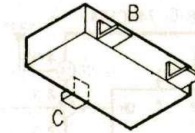
- QF04 ① 5.4V ② 1.8V ③ 4.5V ④ 3.1V ⑤ 3.2V ⑥ 2.5V ⑦ 1.2V ⑧ 1.2V ⑨ 1.0V ⑩ 1.2V ⑪ 2.1V ⑫ 2.3V ⑬ 2.6V ⑭ 1.4V ⑮ 2.6V ⑯ 2.2V ⑰ 2.2V ⑱ 2.1V ⑲ 2.9V ⑳ 0.6V ㉑ 1.8V ㉒ 2.8V ㉓ 1.2V ㉔ 3.8V ㉕ 2.0V ㉖ 1.2V ㉗ 5.4V ㉘ 5.4V

PUI6 CONTROL/DECODER COMPONENT SIDE

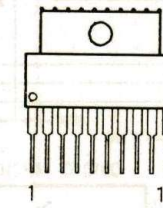
QF11 QM02 QM09 QM06 QM08 QM04
 QM01 QF09 QM05 QM07 QF12 QF01 QF10
 QF02 QF08 QF04 QF06
 QM03 QF16 Q505 Q502
 QF05 QF13 QF14 Q504 Q506 Q501 Q503



PST523D
2SA1005L/K

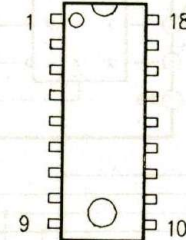


DTA114YK, DTA114EK
DTC144EK, DTC114EK



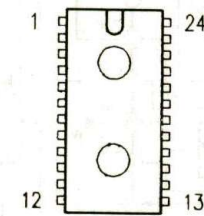
LB1645N

TOP VIEW

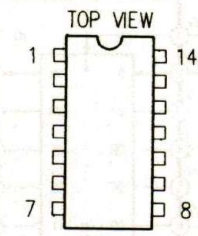


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MN4264P-15

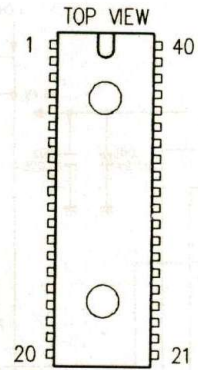
TOP VIEW



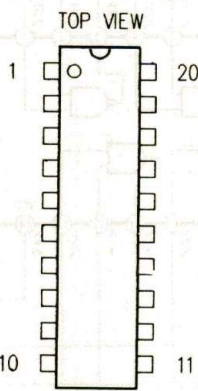
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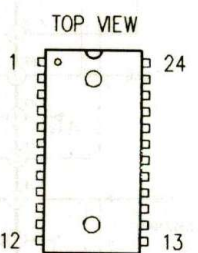
74HC00
74HC74



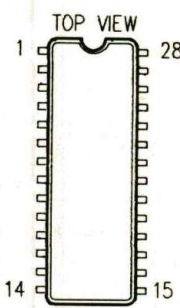
SAA7210



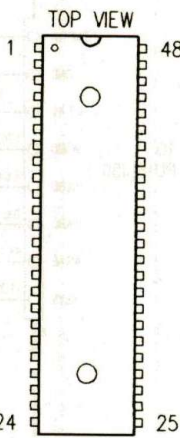
74HC373



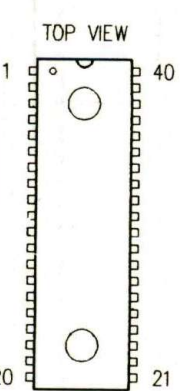
MSM2816A



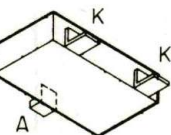
M27128A-2F1



MC68HC11A0P



MC68HC24

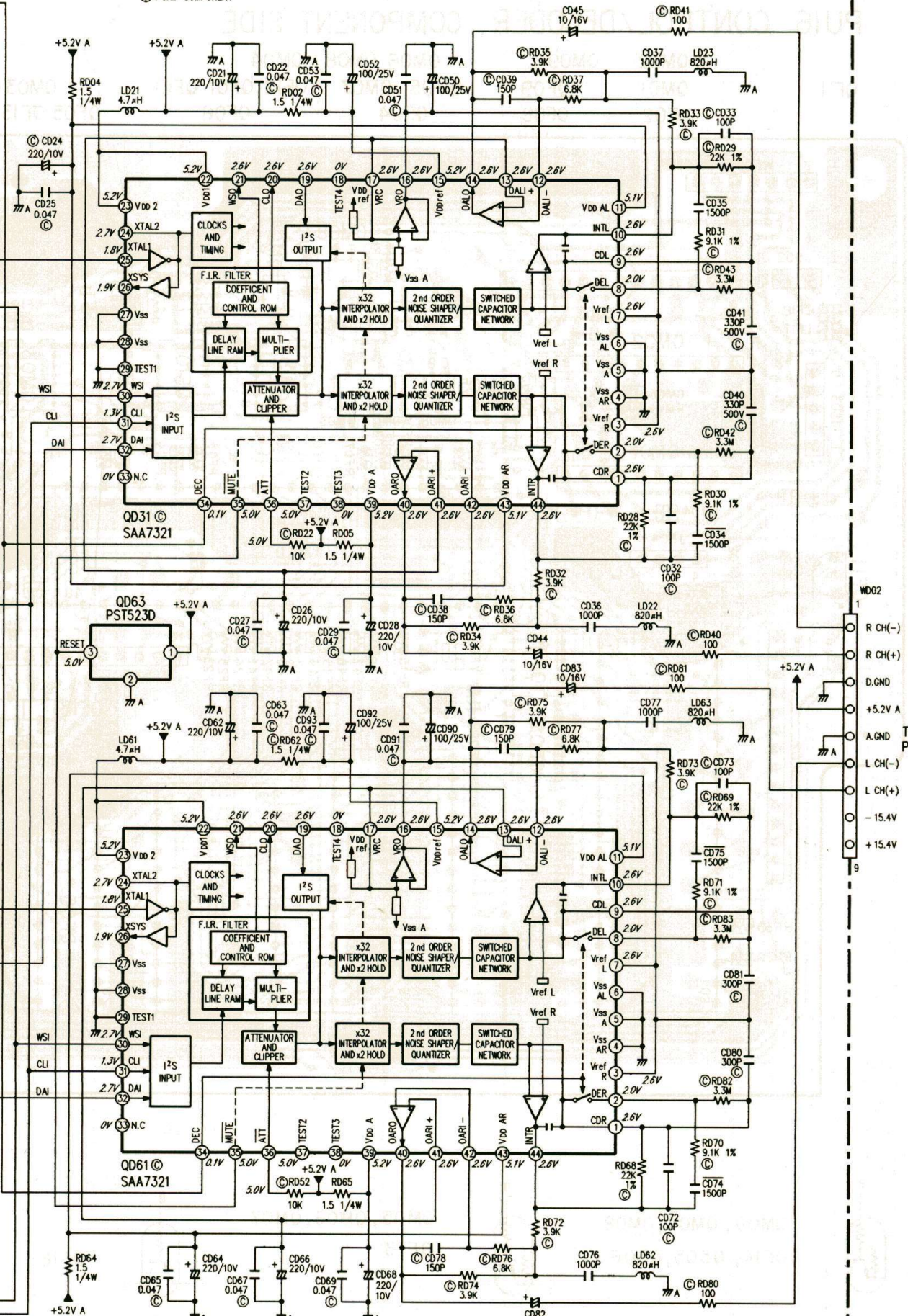
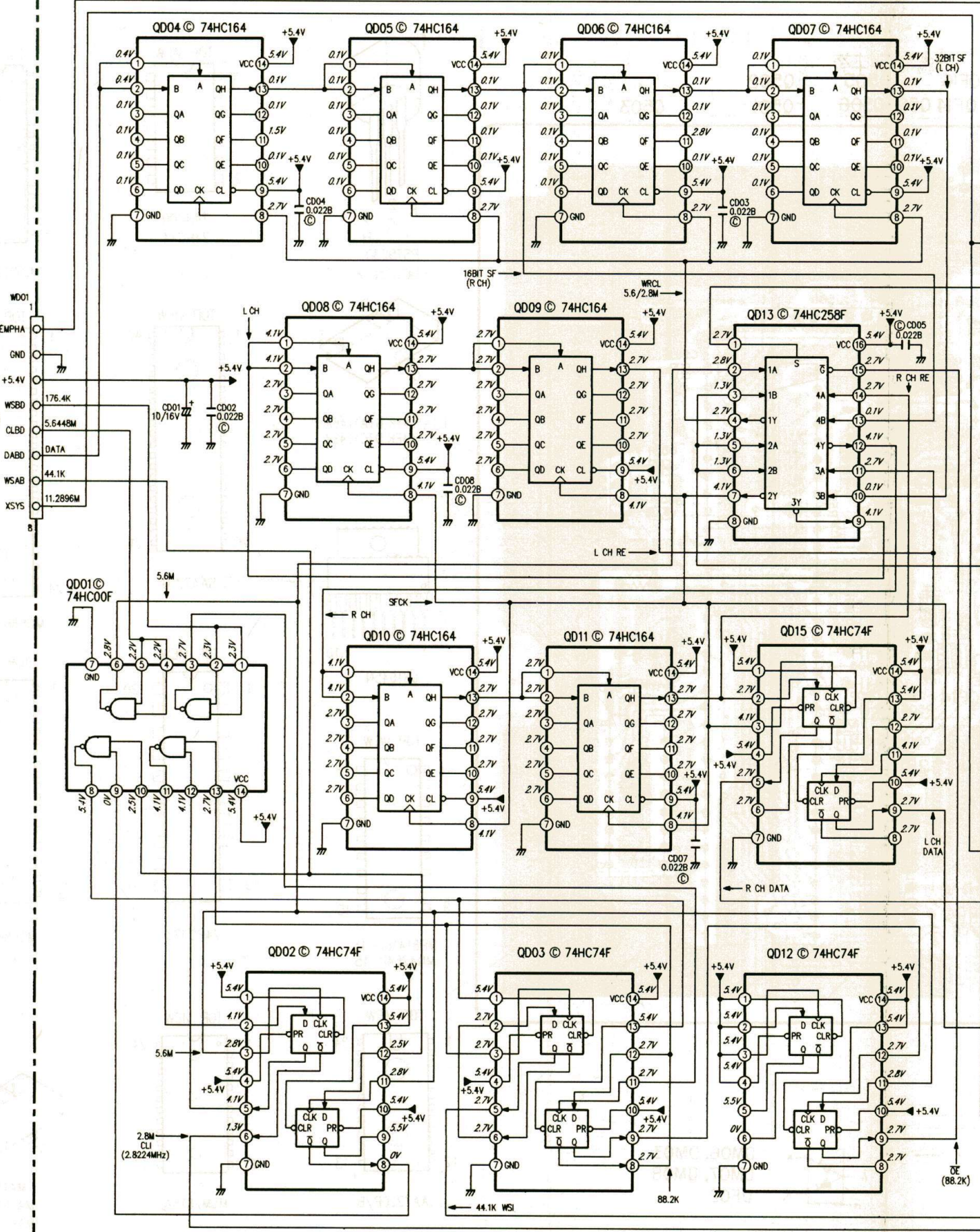


MA153
MA151WA
MA-151K

PD16 DAC

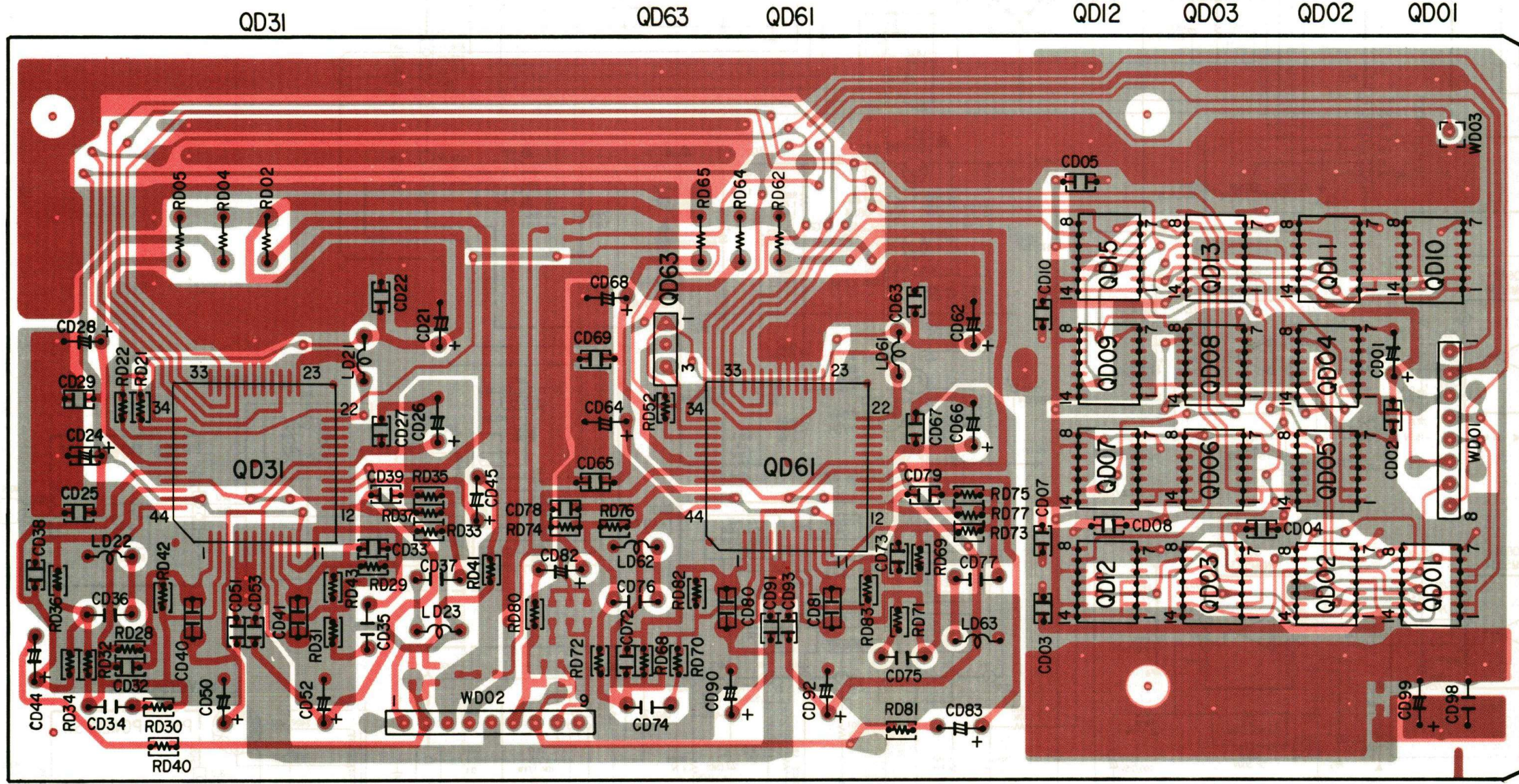
© : CHIP COMPONENT

TO PU16(J501)
WD01
EMPHA
GND
+5.4V
WSBD 176.4K
CLBD 5.6448M
DABD
WSAB 44.1K
XSYS 11.2896M

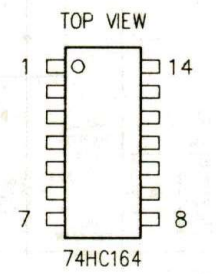
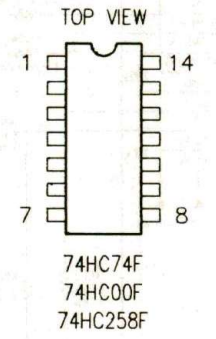
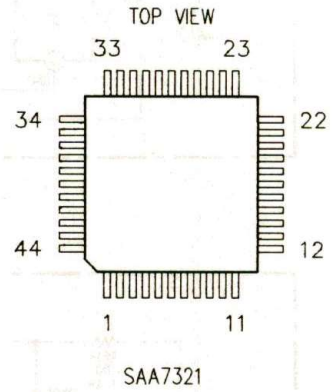


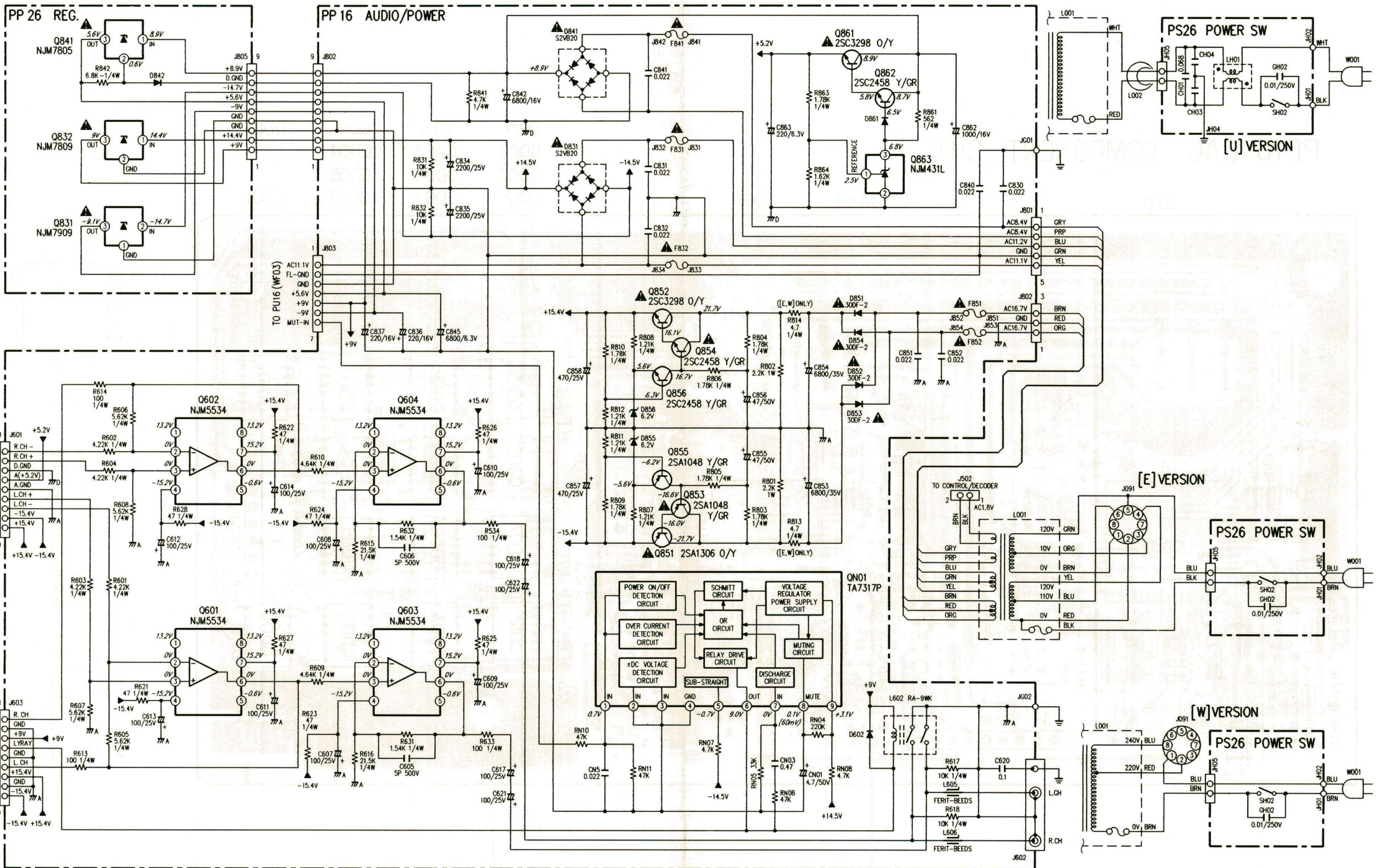
WD02
R CH (-)
R CH (+)
D.GND
+5.2V A
A.GND TO PP16(J601)
L CH (-)
L CH (+)
-15.4V
+15.4V

PD16 DAC COMPONENT SIDE



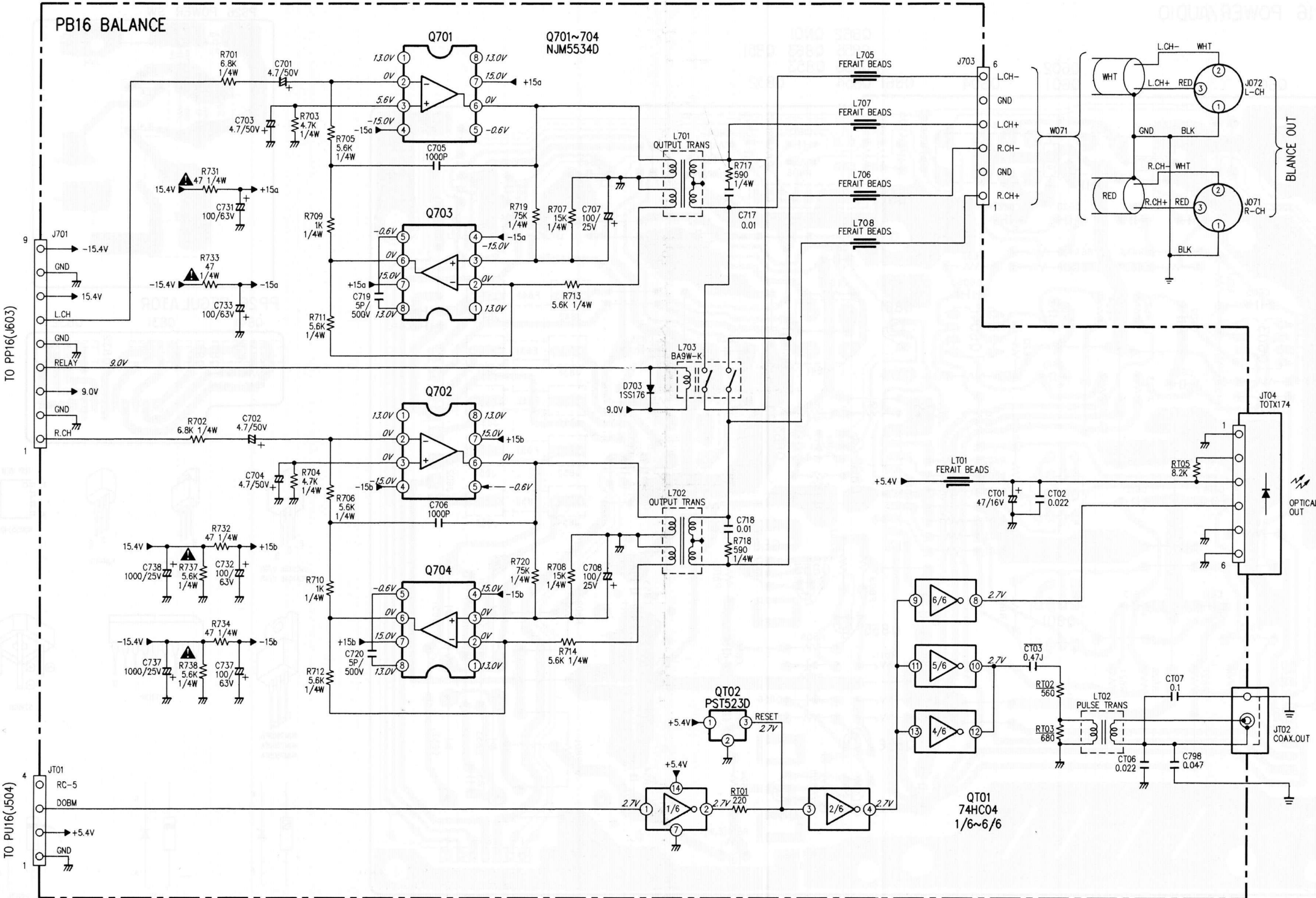
QD15	QD13	QD11	QD10
QD09	QD08	QD04	
QD07	QD06	QD05	
QD12	QD03	QD02	QD01





NOTE ON SAFETY:
 Symbol ▲ Fire or electrical shock hazard. Only original parts should be used to replace any part marked with symbol ▲. Any other component substitution (other than original type), may increase risk of fire or electrical shock hazard.

PB16 BALANCE



PB16 BALANCE

Q703

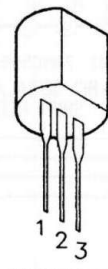
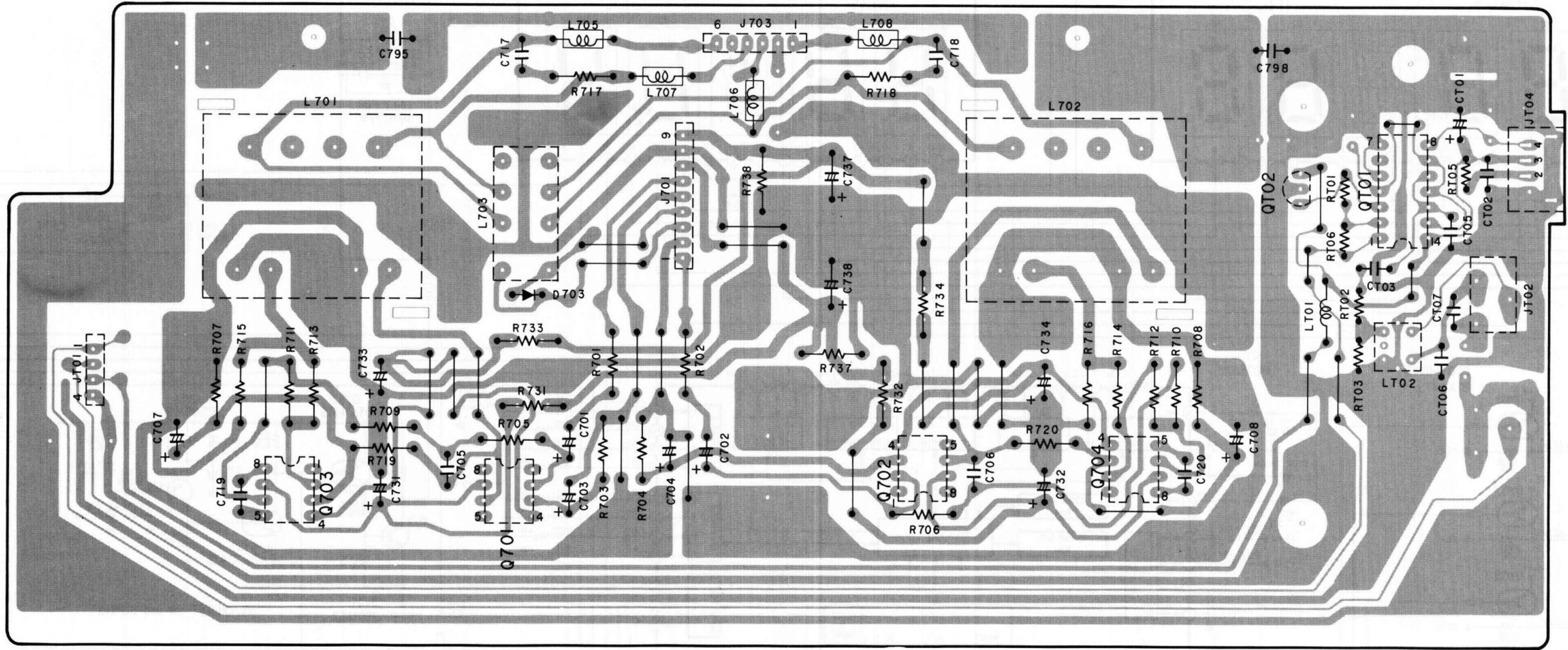
Q701

Q702

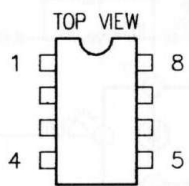
Q704

Q702

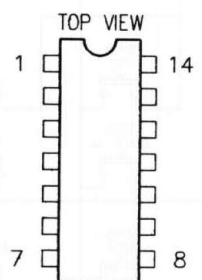
Q701



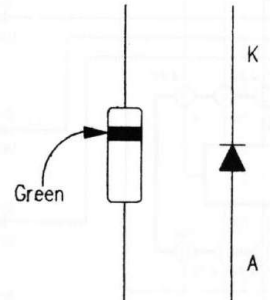
PST523D



NJM5534D

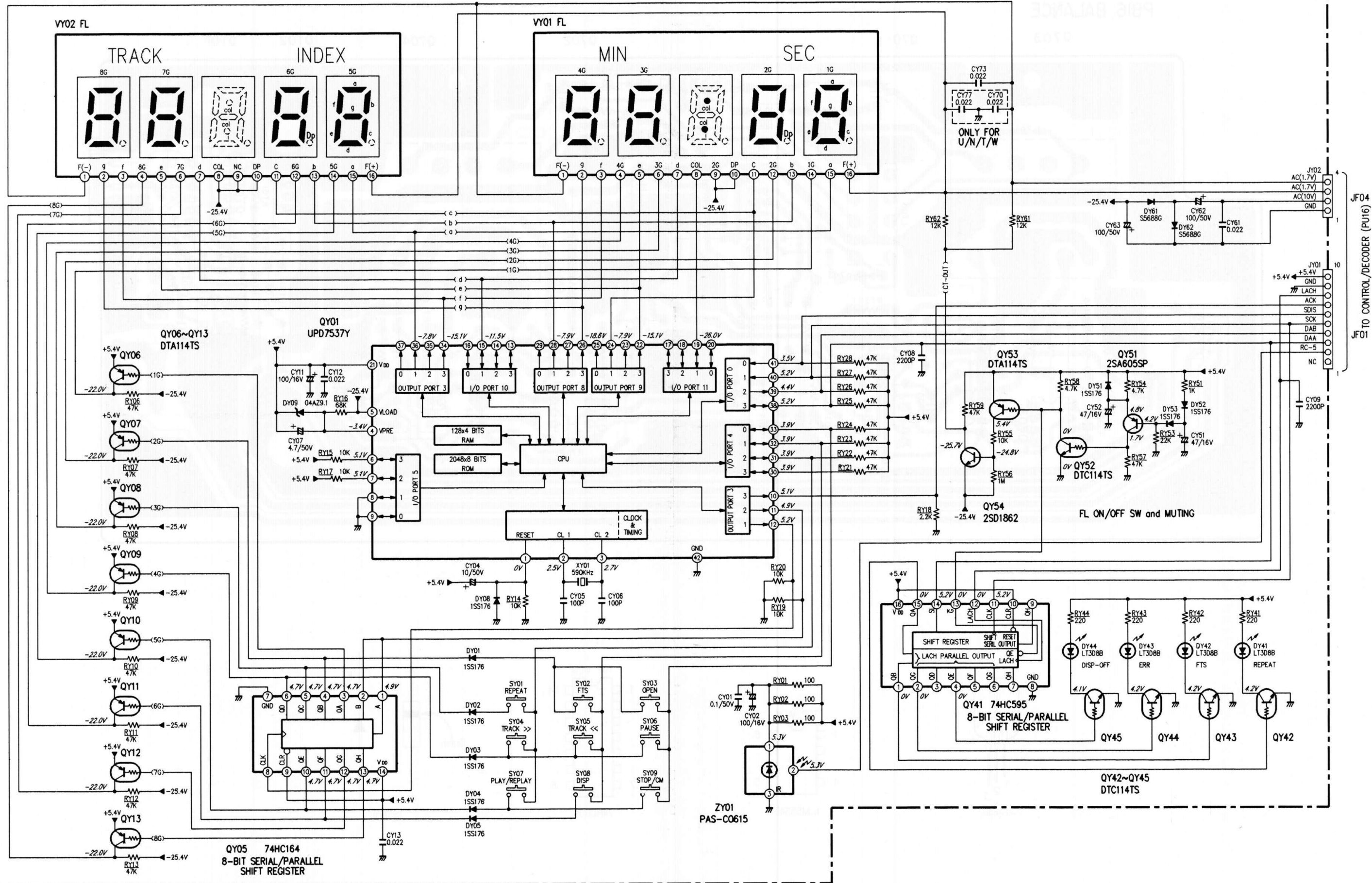


74HCU04



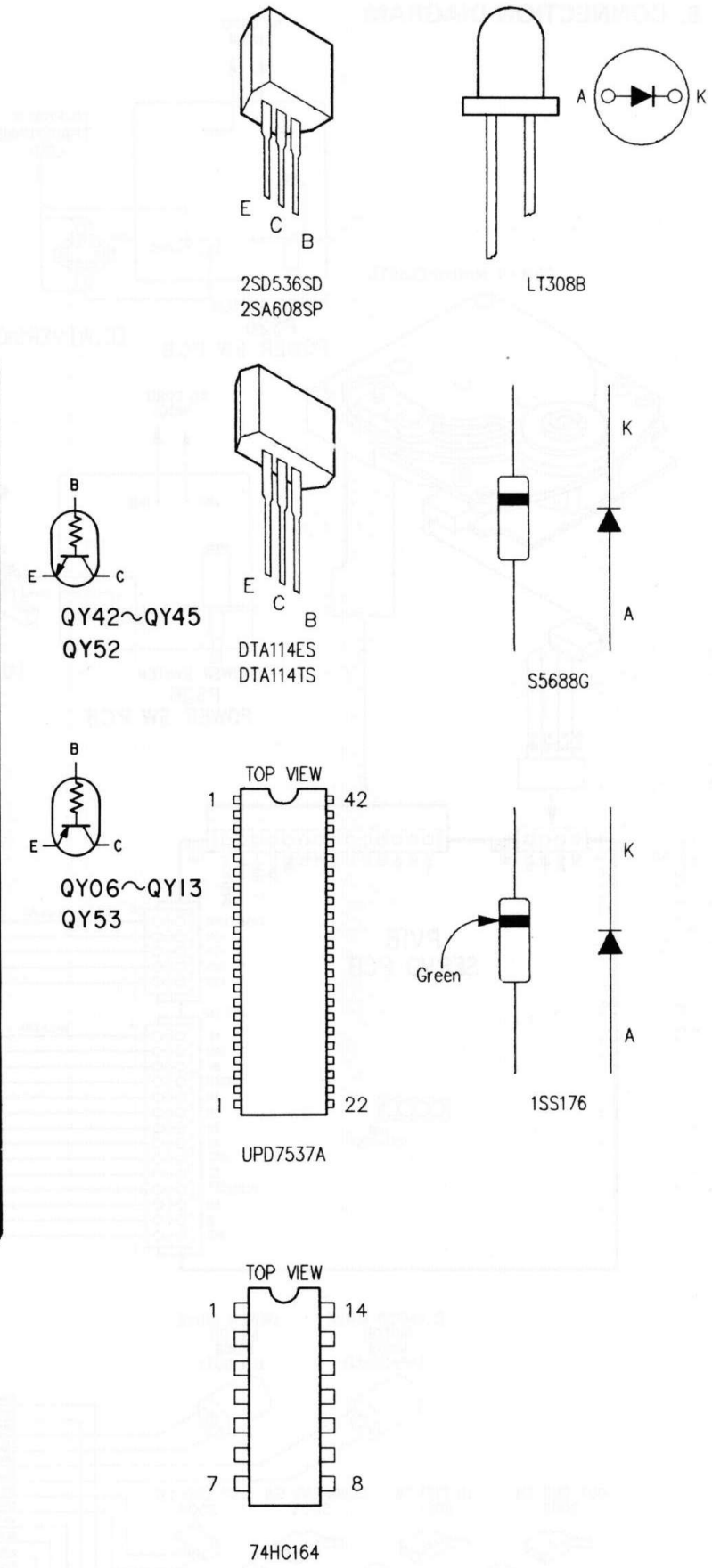
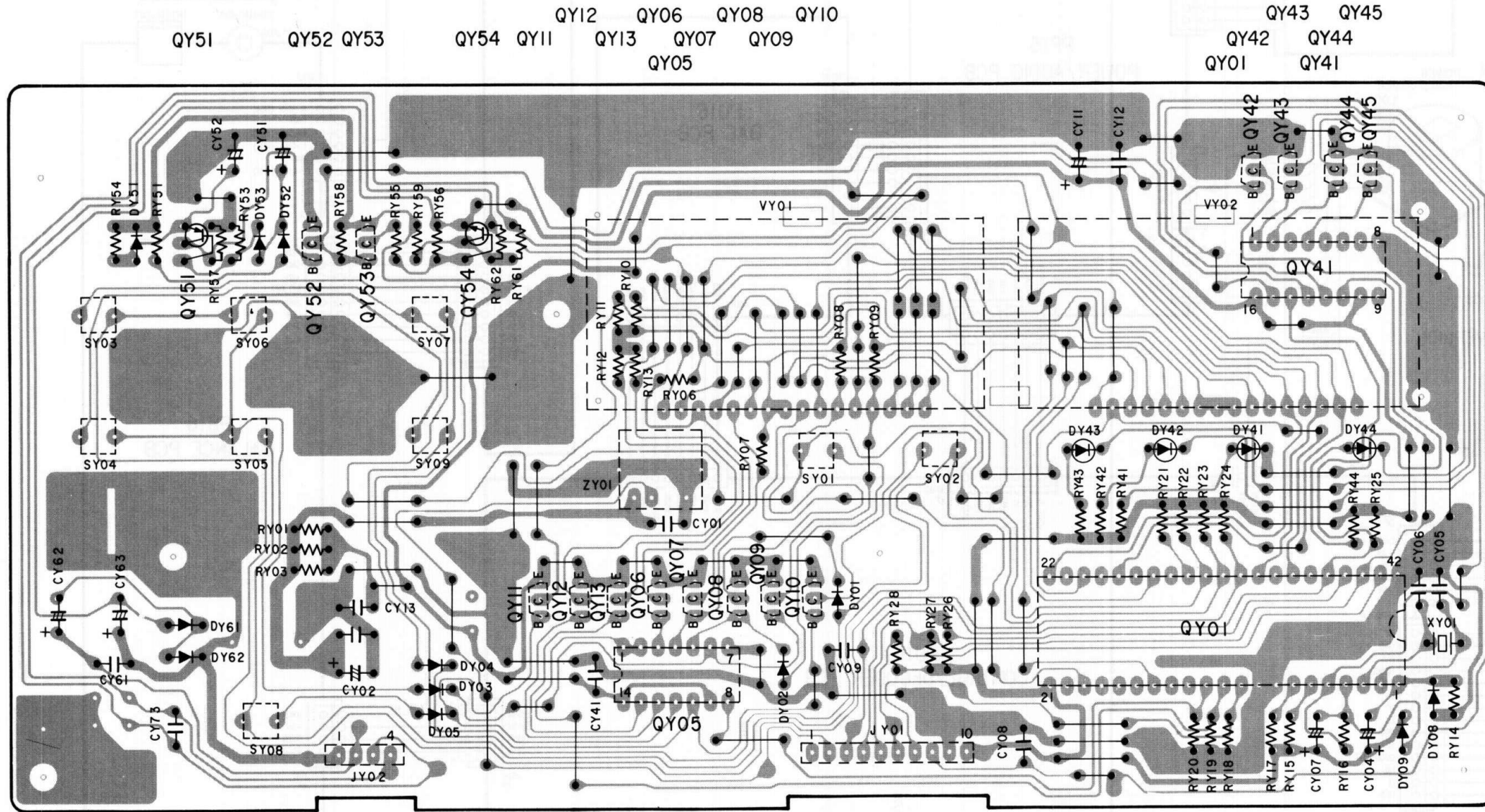
1SS176

PY16 KEY-SENS/DISPLAY

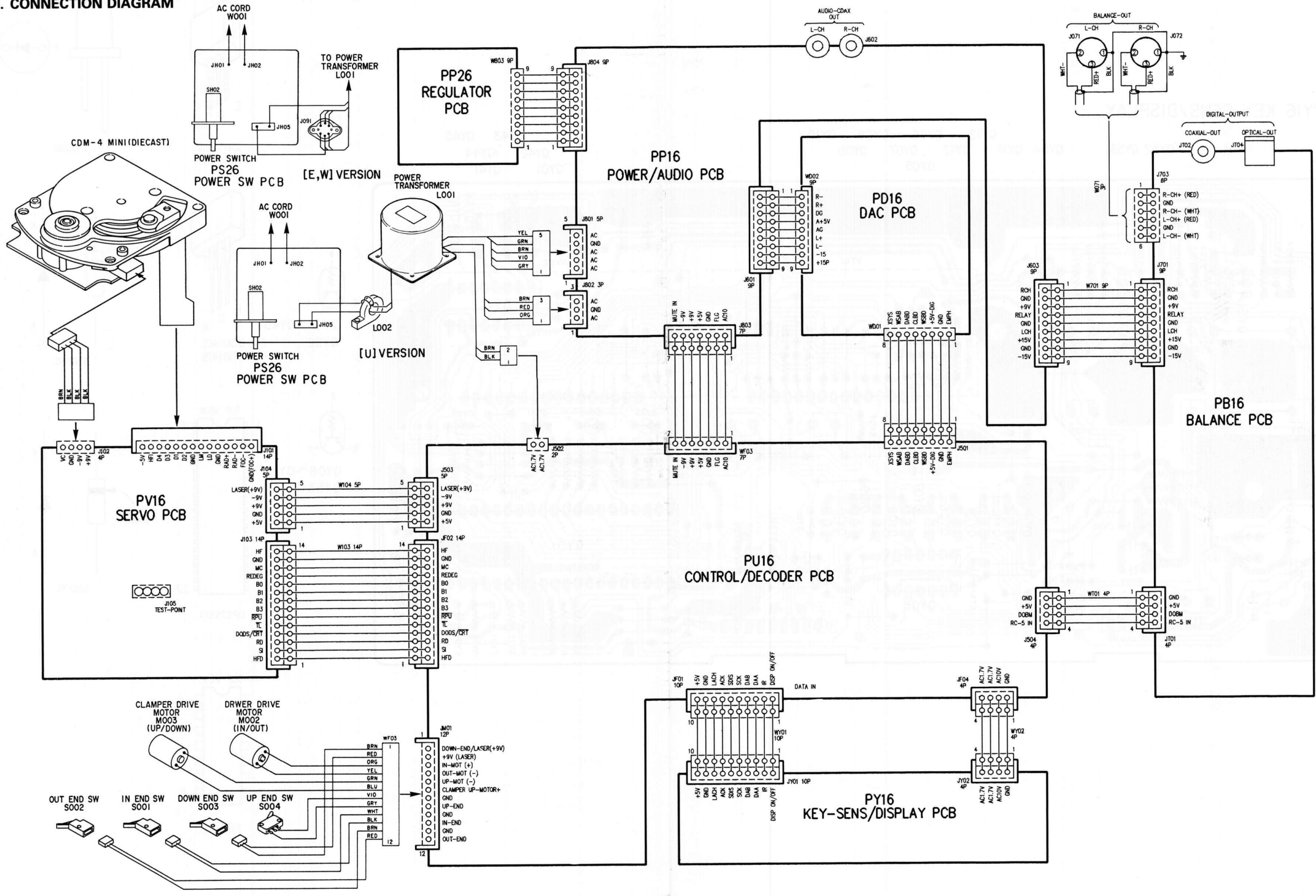


JF04
TO CONTROL/DECODER (PU16)
JF01

PY16 KEY-SENS/DISPLAY



5. CONNECTION DIAGRAM

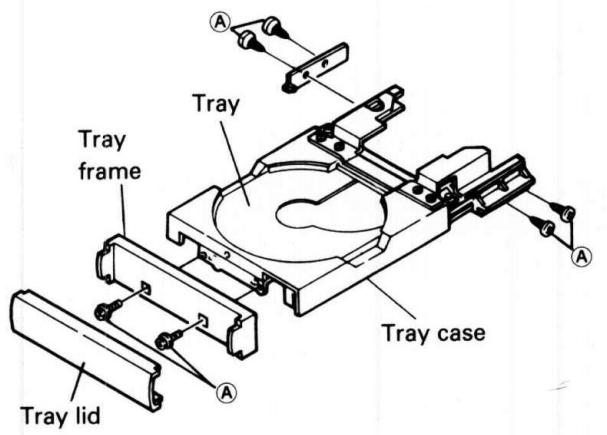


7. TRAY MECHANISM LOADING PROCEDURES

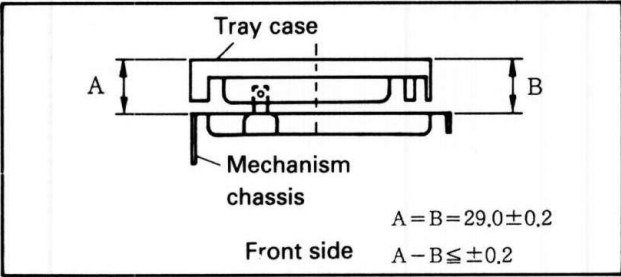
Cautions when servicing

1. When mounting tray and tray case (when replacing tray case because of damage etc.)

a) When the tray has been positioned improperly with a deviated clearance to the front panel window, remove the tray lid, loosen screws (A) and adjust by moving the tray frame within the range of the holes play.

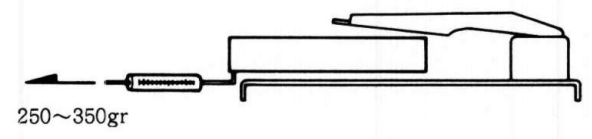


For the tray tilt adjustment, refer to the figure below.

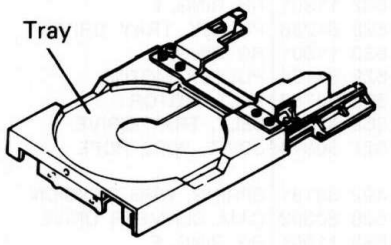


Adjust the tilt with screws (A).

b) The operating power of the tray is set to 250 - 350gr (Power OFF).



2. When the tray is disengaged to the lower side

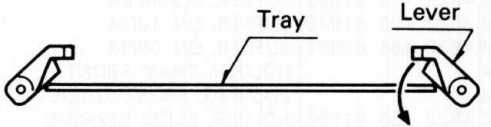


When the tray is pushed downward without the sub-chassis (CDM-4), it will be disengaged. So care will be necessary.

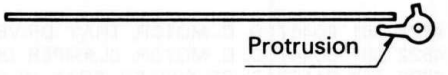
(Closing the tray without the sub-chassis also disengages the tray.)

Mount the tray referring to the figures below.

a) Bring down the lever and put the tray on the protrusion of lever.



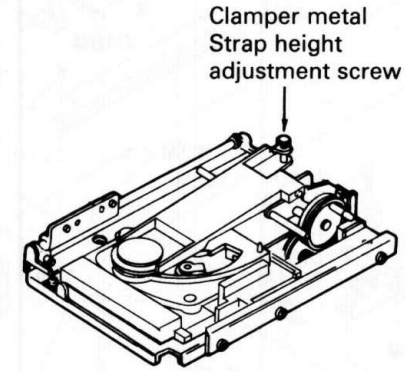
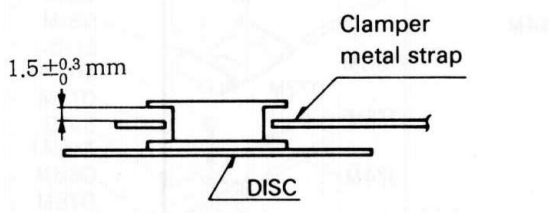
b) While holding the tray, bring down the opposite lever and put the tray on the protrusion of the lever.



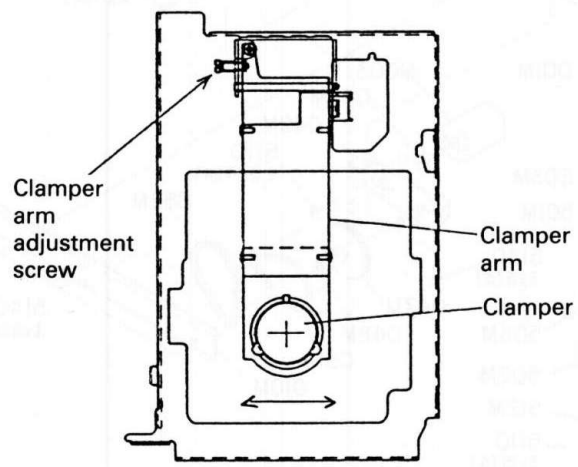
Note:
If both the levers are brought down at the same time, the tray cannot be raised. The levers should be brought down one by one.
If the tray is forced to move to the original position, the two pins injected into the tray case may be bent.

3. When replacing the sub-chassis (CDM-4)

a) The height of the sub-chassis turn table is different one by one. Adjust each turn table height so that the magnet clumper does not touch the clumper metal strap as shown in the figure. Standard (1.5 ± 0.3 mm)

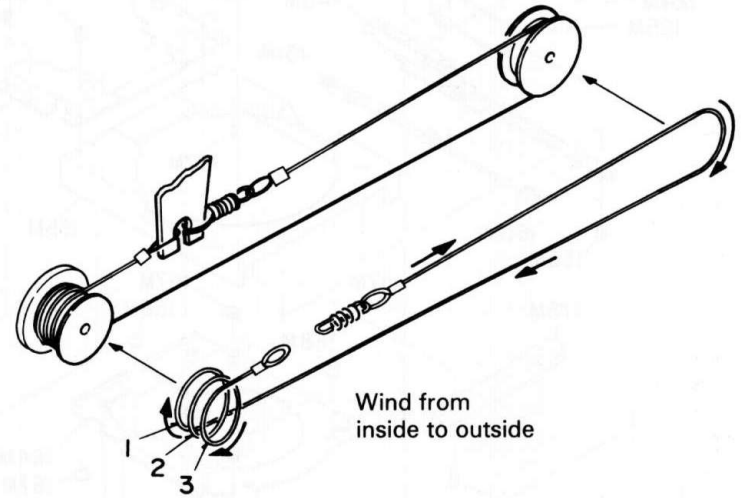


b) After replacing the sub-chassis, readjust so that the magnet clumper does not touch the clumper metal strap at right and left sides. (The clumper metal strap should not be touched to other straps.)



4. Others

a) For the loading wire winding, refer to the figure below.



b) When the magnet clumper (094M) is replaced, bent the narrowest tab and remove the clumper.



Bend the narrowest tab.

8. PRACTICAL HINTS

Test discs

It is important that the test discs be treated with great care.

The disturbances on the discs (black spots, finger-prints, etc.) are exclusive and are unambiguously positioned. Damages may cause extra drop-outs etc., thus putting an end to the exclusivity of the intentional error on the disc.

In that case it is not possible anymore to check for example the good functioning of the track detector.

Measurements on op-amps

In the electronic circuits, op-amps have frequently been used. The applications include amplifiers, filters, invertors and buffers.

In those cases where in one way or the other feedback has been applied, the voltage difference at the differential inputs converges to zero.

This applies to both DC and AC signals.

The cause can be traced to the properties of an ideal op-amp ($Z_i = \infty$, $G = \infty$, $Z_o = 0$).

If one input of an op-amp is directly connected to ground, it will be virtually impossible to measure at the inverting and non-inverting inputs.

In such cases only the output signal will be measurable.

That is why in most cases the AC voltage at the inputs will not be given.

The DC voltages at the inputs are equal.

Stimulating with "0" and "1"

During faultfinding it is sometimes necessary to connect certain points to ground or to supply voltage.

As a result certain circuits can be brought in a desired state, thus shortening the diagnosis time.

In a number of cases the relevant points are outputs of op-amps.

These outputs are short-circuit-resistant, that is, they can be brought to "0" or ground without problems.

The output of an op-amp, however, should never be connected directly to the supply voltage.

Measurements on microprocessors

Inputs and outputs of microprocessors should **never** be connected directly to the supply voltage.

The inputs and outputs should only be brought to "0" or ground if this is stated explicitly.

Measurements with an oscilloscope

During measurements with an oscilloscope it is recommended to use a 1:10 test probe, since a 1:10 probe has a considerably smaller input capacitance than a 1:1 probe.

Selection of the ground potential


It is very important to select a ground point that is as close as possible to the test point.

Conditions for injection

- Injection of levels or signals from an **external** source should **never** take place if the relevant circuit has no supply voltage.
- The injected levels or signals should **never** be greater than the supply voltage of the relevant circuit.

Indication of the test points

In the drawing of the diagrams and PCBs the test points are indicated by a number (e.g. 12) to which the measuring method refers.

In the following measuring method the symbol  has been omitted for the test points indicated.

GENERAL CHECK POINTS

In the detailed measuring method below, a number of general conditions, required for a properly functioning set, will not be mentioned.

Before the detailed measuring method is started, these general points should be checked:

- Ensure that the disc and objective are clean (remove dust, fingerprints, etc.) and use undamaged discs.
- Check that all supply voltages are present and that they have the correct values.

Initiation of the service programme of the μP

For the initiation of the service programme of the μP , see detailed measuring method for the decoder circuit: Initiating the service programme.

SERVICING THE CDM UNIT

If the CDM is malfunction, replace whole, CDM unit.

9. MEASUREMENTS AND ADJUSTMENT

Check of the laser supply

The laser and the laser supply in Q101 plus the monitor diode form a feedback system. A defect in the laser supply may result in the destruction of the laser. If, in that case, the laser (= complete CDM unit) is replaced, the new laser will also become defective. However, it is impossible to check and repair a feedback system if a link is missing. For this reason the laser supply can be checked with the circuit below. The green LED replaces the laser, the voltage across the 18-Ohm resistor is fed back as monitor voltage, the 33-Ohm resistor and the switch serve to draw more current from the laser supply.

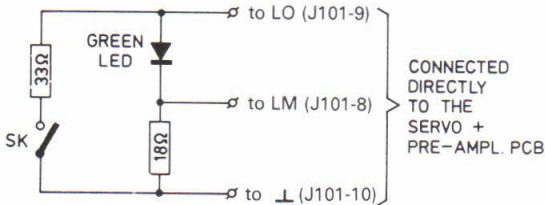


Fig. 4

LED GREEN e.g. CQY 94 IV 5322 130 32182

The above circuit is connected to connector J101 via an extension cable instead of a flex print. The normal flex print is not suited for this purpose because of its high internal resistance.

Code no. extension cable 4822 322 40066

- The above flex print out of connector J101 on the servo + pre- amplifier PCB.
 - Connect the circuit via the extension cable to connector J101.
 - Select the play mode by grounding Si (pin 20 of Q101).
- Note:** Si = 0, start initialization low, is the play mode.
- Measure the voltage LO (Laser Out) at test point 9.

SK open: 1,8 V LO 2,3V
170 mV LM 220 mV
The green LED emits little light.

SK closed: 1,8 V LO 2,3 V
170 mV LM 220 mV
The green LED emits little light.

- During the change- over from SK closed to SK open, the LED will emit more light for a short moment.
- The control sees to it that the same amount of current flows through the LED when SK is open and when SK is closed.

At $\bar{S}_i = 1$, in the STANDBY state, LO = 0V \pm 0,2 V.

Repair procedure

Since laser, monitor diode and photodiodes are very sensitive to static charges, care should be taken that during measurements and adjustments the aids and yourself have a potential that is equal to that of the CD mechanism.

Laser adjustment for CDM4

- Measure the resistance of R108 + R134 with an ohmmeter and adjust potentiometer R134 so that R134 + R108 have a combined value of 1 k Ω .
 - Check the monitor diode connections. Measure at test point 11 and ground (\perp).
 - Put test disc 5 on the turntable.
 - Switch on the set and select the PLAY mode or a similar service position.
 - Take a DC voltmeter and measure across R116. The voltage across this resistor should **stay smaller than 1260 mV**.
 - Check if HF is present. IF not, stop the measurement immediately and analyse the fault.
 - If HF is present, play track 1 of test disc 5 and adjust the sum HF across R114 (test points 1 and 2) to 50 mV with a DC voltmeter.
- Check, during the adjustment, that the voltage across R116 does not exceed 1260 mV.**
- If the adjustment is not successful within the 1260 mV margin across R116, check the angle setting.

Adjustment of the focus off-set (FE lag) R136

Coarse adjustment

- Place potentiometer R136 approximately in mid-position.
 - Put test disc 5 on the turntable.
 - Bring the player in **service position 1**.
 - The focussing motor can now start focussing and when it has found the focal point a "1" will appear on the display.
- Place with potentiometer R136 the focussing motor in optical horizontal position.
 - Hereafter the fine adjustment of the focus offset has to be carried out.

Fine adjustment

- Bring the player in **service position 2**.
- Adjust potentiometer R136 for a voltage across C106 (testpoint 27) of 400 mV \pm 40 mV.

Note:

Notice that the CDM is in a horizontal position.

DETAILED MEASURING METHOD FOR THE SERVO + PRE-AMPLIFIER CIRCUIT

PHOTODIODE SIGNAL PROCESSOR IC (Q101)

• **$\bar{S}i$ (pin 20; test point 21)**

LO (pin 17; test point 9)

LM (pin 16; test point 11)

- With the $\bar{S}i$ signal (=Start Initialization) the laser supply, among other things, is switched on. When the $\bar{S}i$ signal is "low", the LO signal (=Laser Out) should be "high".
- Via the LM signal (=Laser Monitor) the power supply for the laser diode is controlled.

Position of player	POWER ON	Servicing pos. 1*)	PLAY
$\bar{S}i$ signal	"high"	"low"	"low"
LO signal	"low"	"high"	"high"

*) To ensure that the player stays in **servicing position 1**, there should be a disc on the turntable.

To check the laser supply, see "CHECK OF THE LASER SUPPLY"

• **FE (pin 5; test point 26)**

- The FE signal (=Focus Error) is used to drive the focusing unit. When the $\bar{S}i$ signal goes "high", the focal point will be searched for.
- When the player is brought into **servicing position 1** without disc, the objective will search for the focal point. At test point 26 the FE signal varies between +3 V and -3 V.
- The FE signal ensures that the spot stays in focus. When an error signal is injected, the FE signal will correct. Bring the player in **servicing position 2** (with disc on turntable).

Inject successively a voltage of +5 V and -5 V (= +1B and -1B) via a 200 k Ω resistance to testpoint 25 and check the FE signal.

Signal injected testpoint 25	+5 V	-5 V
FE signal : test point 26	negative	positive

• **FE lag (pin 6; test point 27)**

- See adjustment of the focus off-set.

• **RD signal (pin 21; test point 24)**
HIGH-OHMIC MEASUREMENT

The RD signal (= READY) goes "high" when the starting procedure of Q101 has been completed.

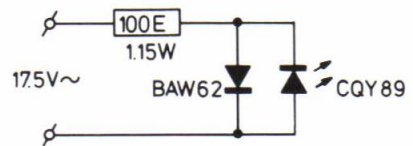
Position of player	POWER ON	Servicing position 1	PLAY
RD signal	"low"	"high"	"high"

- **D1 (pin 9; test point 4)**
- **D2 (pin 10; test point 6)**
- **D3 (pin 8; test point 7)**
- **D4 (pin 7; test point 8)**

- The signals D1+D4 are the error signals from the photodetector circuits.
- When in servicing position 1 the disc is moved, the focusing unit should keep in track. When the disc is moving, there should be a changing signal on test points 4, 6, 7 and 8.

- **Check of the photodiodes**

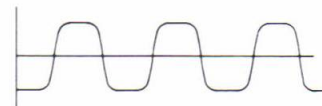
Connected the circuit below to an alternating voltage of 17,5 V.



- 100 E-1.15 W - 4822 116 51098
- BAW 62 - 4822 130 30613
- CQY 89 - 4822 130 31332

Switch on the supply voltage and bring the player in the stand-by mode or in **servicing position 0**. In this measurement, infrared diode CQY89 replaces the function of the laser diode.

When this diode is held above the objective unit, the infrared light falls on the 4 photodiodes. When the 4 photodiodes are functioning, the following voltage form will be visible on test point 4, 6, 7 and 8 on the servo + pre-amplifier PCB. (the amplitude depends on the distance between the IR diode and the objective).



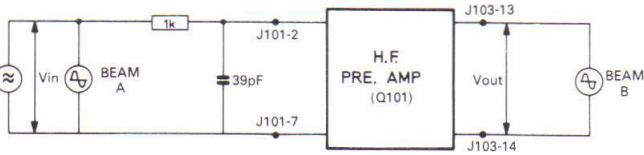
Position of the oscilloscope: 100 ms/div.

•HF-in (pin 3, test point 3)

- The HF-in signal (=High Frequency in) is the information signal from the 4 photodiodes.

Check of the HF amplifier in Q101

- Take the flexible PCB out of connector J101.
- Switch on the supply voltage.
- Inject a signal V-in of about 10 mVpp, 50 kHz, via the RC network, between connector pin J101-2 and connector pin J101-7 according to the diagram below.
- The output voltage between connector pins J103-13 and J103-14 should be about 1 Vpp.



•HF-out (pin 27; measure at connector pin J103-14)

- The HF-out signal (=High-Frequency) is the amplified information signal for the decoder circuit. During playback of test disc no. 5 (4822 897 30096), a so-called "eye pattern" should be present on test point 17 (see figure below).
- The HF signal should be present and stable in: the PLAY mode and in **servicing position 3** after the lead-in track has been read. In **servicing position 2** and during the reading of the lead-in track, the HF signal is present, but is not stable.



Position of the oscilloscope: 0,5 μs/div.
Amplitude about 1,5 Vpp.

**•DET (pin 26)
HFD (pin 19; test point 23)
TL (pin 18; test point 16)**

- The DET signal (=Detector) gives information on the level of the HF signal to the high-frequency Level/Drop-out detector of Q101.
- When the level of the HF signal is too low, the HFD signal (=High-Frequency Detector) will go "low".
- The TL signal (=Track Lost) will then go "low" in order to tell the servo μP that the tracking signals are unreliable.

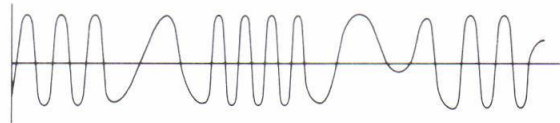
*Method:
(Can only be used in a playing set).*

- Put test disc 5A (4822 397 30096) on the turntable.
- Switch on the power-supply switch and press the PLAY key.
- Play track number 10 or 15 and check the HFD signal at test point 23. When drop-out pulses are present on the DET signal (pin 26), the HFD pulses should also be present at test point 23. (Position of oscilloscope: 2 ms/div).

When the disc is slowly braked by hand, \overline{TL} pulses will be visible at test point 16.

**•RE 1 (pin 11; test point 18)
RE 2 (pin 12; test point 22)**

- Signals RE1 and RE2 (Radial Error) are the control signals for the arm during tracking.
- In **servicing position 2**, the following signals should be visible at test point 18 and 22:



Position of the oscilloscope: 2ms/Div.
The frequency strongly depends on the eccentricity of the disc.

• \overline{DODS} (pin 24: test point 19)

The \overline{DODS} signal (= Drop Out Detector Suppression) avoids that Drop-Out signals influence the arm control during track jumping.

**•SC (pin 25)
SC (=Start Capacitor)
HIGH-OHMIC MEASUREMENT**

Position of player	SC (pin 25)
POWER ON	-4 V
PLAY	+5 V
Servicing pos. 1	+5 V

•FE lag (pin 6, test point 27)

- In **servicing position 2, 3** and in the PLAY mode, a voltage of about 400 mV is present at this point. When the disc is moved by hand in service position 1, the FE lag will vary.

•Check the signals coming from the servo μ P and from photodiode signal processor Q103.

•RE-dig (pin 3; test point 37)

- With the RE dig signal (= Radial Error digital = Radial Polarity), the movement of the arm is controlled/corrected in case of track jumping and bumping against the player).
- In **servicing position 3** or in the PLAY mode a square wave should be present at test point 37. Because of frequency variations this square wave is hard to trigger.
- In the positions "SKIP \lll " and "SKIP \ggg " the frequency of the square wave decreases.

•DAC (pin 10; test point 38).

With the DAC signal (= Digital to Analogue Converter) the track jumping speed is controlled. This signal is derived from the signals B0 + B3 coming from the decoder μ P.

•RE (pin 7; test point 39)

- With the RE signal (= Radial Error) the light spot is kept on the track. When an error signal is injected, the RE signal will correct.
- Bring the player in **servicing position 3**.
- Inject successively a voltage of +5 V and -5 V (= +1B and -1B), via a 120 k Ω resistance, to pin 5 of Q106 and check the RE signal.

Signal injected test point 38	+5 V	-5 V
RE signal	Negative	Positive

•RE lag (pin 8; test point 41)

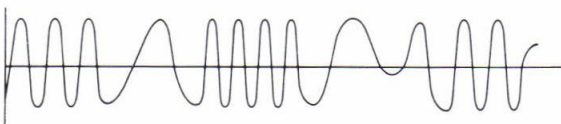
Capacitor C121 in the RE-lag circuit has a memory function. It memorizes the degree of inclination of the disc. When a jump is made to a certain track on the disc, the memory should be cleared. This takes place by the decoder μ P (RP \bar{U} signal) via transistor Q104.

During track jumping (SEARCH), slow pulses should be visible at test point 43 (position of the oscilloscope 0,1 ms/Div). In that case pulses should also be visible on the collector of transistor Q104.

•RE 1 (pin 20; test point 18)

•RE 2 (pin 1; test point 22)

- Signals RE1 and RE2 (Radial Error) are the control signals for the arm during tracking.
- In servicing position 2, the following signals should be visible at test point 18 and 22.



Position of the oscilloscope: 2 ms/Div.-Ac. The frequency strongly depends on the eccentricity of the disc.

- B0 (pin 12; test point 36)
- B1 (pin 13; test point 34)
- B2 (pin 14; test point 33)
- B3 (pin 15; test point 32)

With the B0 + B3 signals

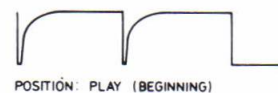
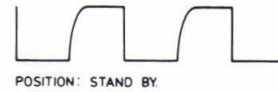
- The radial control is switched on and
- The level on the DAC output is controlled.
- In the SEARCH mode, there should be activity on all 4 test points.

	STOP	PLAY	SERVICING POSITION 0,1,2 SEARCH \lll	SERVICING POSITION 0,1,2 SEARCH \ggg
B0	"low"	"high"	"low"	"high"
B1	"high"	"high"	"high"	"low"
B2	"high"	"high"	"high"	"high"
B3	"low"	"low"	"low"	"low"

•MCES (test point 12)

The MC signal (= Motor Control) is used to control the speed of the turntable.

- In the standby position (= power on), a signal as shown in the figure below is present at test point 12. The frequency is 88,2 kHz.
- With a disc on the turntable and with the player in service position 3 or in the PLAY mode, a signal as shown in the figure below should be present at test point 12. The frequency is 44,1 kHz.



When the MCES signal is correct the turntable motor must be rotating.

•VC (connector point J102-1)

Fast check.

- Place a disc on the turntable. The voltage at connector point J102-1 will be about $V_c = 0 > V_c > -1.7$ V during playback.

DETAILED MEASURING METHOD FOR THE DECODER CIRCUIT

Initiating the service programme

Service position "0"

- Press "STOP", "PLAY" and "FTS" while switching on the mains voltage.
- The display shows:
 - The TRACK and INDEX field: LH 1
 - The minutes and seconds field: 00 00.
- Fast CDM check:
 - With "SEARCH ►►" and "SEARCH ◄◄": arm outward and inward. (Remote Control only)
 - Laser control and focus control in.
 - Check that the focus unit jumps over the tracks.

ATTENTION: AFTER ONE OF THESE KEYS (SEARCH) IS PRESSED, THE LASER REMAINS DRIVEN UNTIL SERVICE POSITION 3. THEREFORE, AVOID DIRECT EXPOSURE TO THE BEAM IN SERVICE POSITIONS 0, 1 AND 2.

Service position "1"

- Press "SKIP ►►"
- The display shows:
 - The minutes and seconds field: 00 01;
- Functions:
 - Laser control in;
 - Focus start procedure is repeated unlimitedly;
- With "SEARCH ►►" and "SEARCH ◄◄": arm outward and inward.
- With "SKIP ◄◄" one can go back to service position "0".

Service position "2"

- Move arm inward with "SEARCH ◄◄".
- Put a disc on the turntable.
- Bring player in service position "1"
- Press "SKIP ►►".
- The display shows:
 - The minutes and seconds field: 00 02;
- Functions:
 - Laser control in;
 - Focus control in;
 - Turntable motor control in;
 - Decoder generates MC signal;
- With "SEARCH ►►" and "SEARCH ◄◄": arm outward and inward.
- With "SKIP ◄◄" one can go back to service position "1".

Service position "3"

- Bring the player in service position "2"
Press "SKIP ►►"
- Put a disc on the turntable.
- Press the "PLAY" key.
- Functions: all keys have their original functions.
- If an error is detected, the player will stop and give an error message on the display. For a description of the error message: See Error table.
- If the μ P observes a system error, a system error indication will appear on the display: Er 01 through Er 12.
- If the μ P observes an operating error, an operating error indication will be displayed for 1.5 seconds: Er 30 through Er 57 and Er 60.

The service programme can be abandoned again by turning the mains switch (POWER ON/OFF) off and on again (Hardware reset).

The error message number will be displayed only in service programme. (In normal mode, "ERROR" indication will just appear.)

"SEARCH ►►" = Forward search key

"SEARCH ◄◄" = Reverse search key

"SKIP ►►" = TRACK NEXT key

"SKIP ◄◄" = TRACK PREV key

ERROR TABLE

System errors

Indication	Cause	Check
Er 01	No RD	\overline{Si} , Sc, RD, Photodiode signal processor
Er 02	No \overline{TL} pulse at start-up	\overline{TL} , HF, Photodiode signal processor, CD disc present
Er 03	No lead-in track found	CD disc, radial arm position, REdig, Radial error processor
Er 04	Too many \overline{TL} pulses in PLAY	CD disc, $\overline{HF\overline{D}}$
Er 05	\overline{TL} pulse > 50 msec. in PLAY	CD disc, HF in, photodiodes
Er 06	No \overline{TL} pulse within 0.5 sec. during track jumping	RE-lag circuit
Er 07	Subcoding error during PLAY	HF
Er 08	TOC error	CD disc, turntable motor control, radial arm position
Er 10	Search error: selected point on disc cannot be reached	CD disc
Er 11	EEPROM error: programme deviation	Replace EEPROM
Er 12	RAM in μP MC68HC11 defective	Replace μP MC68HC11
Er 49	FTS selection error: "SKIP $\blacktriangleright\blacktriangleright$ " key actuated at the moment the μP is storing data.	
Er 50	FTS selection error: "SEARCH $\blacktriangleleft\blacktriangleleft$ " key actuated while the CD disc has not yet been stored in the FTS memory; or TOC of the disc has not yet been read in.	
Er 51	FTS selection error: "SEARCH $\blacktriangleleft\blacktriangleleft$ " key actuated.	
Er 52	FTS selection "CANCEL": "CANCEL" key actuated while data are being stored in the memory.	
Er 53	"CANCEL" key actuated, but clear function has not been carried out.	
Er 54	FTS data storage error: TOC of the CD disc, of which data should be saved, has not yet been read in.	
Er 55	FTS playback error: Insufficient data of the TOC of the CD disc read in for processing in the FTS memory. Check the lead-in track.	
Er 56	"A \rightarrow B" key actuated while the player was not in PLAY mode.	
Er 57	"SEARCH" key actuated during "SKIP" mode.	
Er 60	End of the "FAST FORWARD/FAST REVERSE" search motion.	

Operating errors

Er 30	"SKIP $\blacktriangleright\blacktriangleright$ " key operated during the last track, with "REPEAT" turned off.
Er 31	"SKIP $\blacktriangleleft\blacktriangleleft$ " key operated during the first track, with "REPEAT" turned off.
Er 32	Index selected before a track has been selected.
Er 33	The selected index number does not exist on this disc.
Er 34	Programme survey requested; no programme present.
Er 35	The programme memory is full.
Er 36	The programmed track is not present on this CD disc.
Er 37	The selected track is not present on this CD disc.
Er 38	Selected time in seconds greater than 59.
Er 39	Error in the selection procedure.
Er 40	Wrong time programmed.
Er 41	The selected time does not exist.
Er 42	The selected track does not exist.
Er 43	FTS data storage error: memory full.
Er 44	FTS data storage error: no programme presented.
Er 45	FTS data storage error: no more free disc number.
Er 46	FTS playback error: no FTS programme in the memory.
Er 47	FTS selection error: "SKIP $\blacktriangleright\blacktriangleright$ " key actuated while FTS points towards end of the number of tracks.
Er 48	FTS selection error: "SKIP $\blacktriangleleft\blacktriangleleft$ " key actuated while the FTS points to the beginning of the number of tracks.

I MICRO PROCESSOR MC68HC11 (QF01)

● Reset (pin 39; test point 103)

After switching on the supply voltage, a positive voltage should be present.

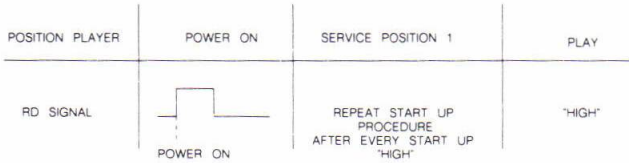
● X-TAL out (pin 30; test point 31)

The frequency of this signal should be 8 MHz.

● RD (pin 18; test point 24)

The RD signal (= Ready) goes "high" when the focal point has been found.

So there should be a disc on the turntable.



● SWAB/SSM (pin 43; test point 78)

When, after RD "high", the SWAB/SSM is "high" for a short moment (> 0.2 sec), the turntable motor control will be switched on.

The turntable motor is controlled by the MC-signal (test point 81).

To check MC, see: "Decoder A IC". To check the turntable motor control, see Servicing the CDM unit: "Checking of the motor control".

● TL (pin 18; test point 16)

- The TL signal (Track Loss) is used to tell the μ P that track loss threatens. The μ P then can give correction signals with B0 + B3.
- In the "SEARCH" mode, or when the player is bumped against, there are pulses on test point 16.

● REdig (test point 37)

The REdig signal (= Radial Error Digital = radial deviation) is used to determine the place of the arm relative to the track and to check/correct in case of track jumping or bumping against the player.

In position PLAY or PAUSE mode, a square wave should be present on test point 37.

Because of frequency variations, this square wave is hard to trigger.

● DODS (pin 13; test point 19)

The DODS signal (= Drop Out Detector Suppression) avoids that Drop-Out signals influence the arm control during track jumping.

● RP/4 (pin 6; test point 94)

RP/4 enables very fast searching in position SEARCH. In that position, there should be activity at test point 94.

● E (pin 27; test point 96)

E is the internal microprocessor block signal of 2 MHz.

● AS (pin 26; test point 97)

AS is the Address Select strobe signal working with a 2 MHz clock frequency.

● Data I (pin 44; test point 98)

● Data O (pin 45; test point 99)

● SCK (pin 46; test point 100)

● ACK (pin 47; test point 100)

After the player is switched on, there should be activity at test points 98 through 101.

II MICROPROCESSOR SLAVE MC68HC24 (QF02)

● Reset (pin 39; test point 103)

When the supply voltage is switched on, a positive voltage should be present.

● Si (pin 21; test point 21)

When the Si signal (= Start Initialization) is "low", the laser supply and the focusing control are switched on.

Position of player	POWER ON	Servicing pos. 1	PLAY
Si signal	"high"	When repeating the start procedure "low"	"low"

● B0 (pin 7 ; test point 36)

B1 (pin 8 ; test point 34)

B2 (pin 9 ; test point 33)

B3 (pin 10; test point 32)

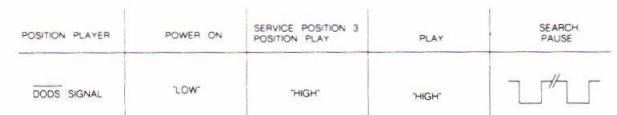
With the B0 + B3 signals

- The radial control is switched on.
- The level on the DAC output is controlled.
- In the SEARCH mode, there should be activity on all 4 test points.
- In the following positions the signals B0 + B3 are stable:

signal	STOP	PLAY	Service pos. 0,1,2 SEARCH <<	Service pos. 3 SEARCH >>
B0	"low"	"high"	"low"	"high"
B1	"high"	"high"	"high"	"low"
B2	"high"	"high"	"high"	"high"
B3	"low"	"low"	"low"	"low"

● DODS (pin 13; test point 19)

The DODS signal (= Drop Out Detector Suppression) avoids that Drop-Out signals influence the arm control during track jumping.



III DECODER-A (Q501)

● Check the MC signal (pin 17; test point 81)

- In stand-by mode, the MC signal (Motor Control) corresponds to the figure below.

Note:

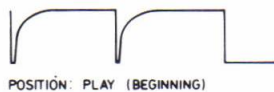
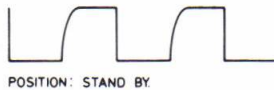
The repetition time of the MC signal is 11.3 μsec.

- Place a disc on the turntable.
- In position PLAY or SERVICE POSITION 2, the MC signal corresponds to the figure below.

Note:

During start-up the duty cycle is 98%, then the duty cycle of the signal becomes about 50%.

See also servicing the CDM unit: "Check of the motor control".



● Check the HF signal on test point 65 (eye pattern)

- Insert a disc.
- The HF signal should be present and be stable in the PLAY mode.
- In SERVICING POSITION 2 and during reading of the lead-in track the HF signal is not stable.

Position of oscilloscope 0.5 μs/DIV.

Amplitude ≈ 1.5 V_{pp}



● Check the HFD signal on test point 66

- Insert a disc.
- In the PLAY mode the HFD signal is "high"; however, minor pulses may be present and in cause of disorders on the disc.
- In SERVICING POSITION 2 and during playback of track no. 15 of test disc 5A HFD pulses are visible.
- When the disc is braked a little, HFD pulses are visible.

Position of the oscilloscope 5 ms/DIV



● Check if the MUTE signal (pin 11; test point 67) is "high"

When Filter-B IC is applied, the MUTE input will not be used.

● Check the CEFM signal (pin 27; test point 68)

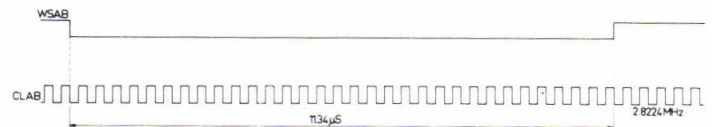
- Place a disc on the turntable.
- In stand-by mode (only the mains switch is depressed), the frequency lies between 2.82 MHz and 5.64 MHz.
- In the position PLAY and SERVICE POSITION 2, the frequency is 4.32 MHz.

● Check the Xin signal (pin 19; test point 69)

- The Xin frequency is 11.2896 MHz.
- If this frequency deviates, check test point 70; Xout signal, on Filter-B IC. This frequency should also be 11.2896 MHz.

● Check the timing signals meant for Filter-B IC

- Place a disc on the turntable.
- Select one of the following positions: SERVICE POSITION 2, or position PLAY.
- Trigger the oscilloscope with the WSAB signal (test point 71; pin 39).
- Check signals:
 - WSAB at test point 71 (pin 39) (Word Select from Decoder-A to Filter-B)
 - CLAB at test point 72 (pin 38) (Clock from Decoder-A to Filter-B)
 and their interrelation.
- There must be activity at test point 73 (pin 37), DAAB signal (DATA from Decoder-A to Filter-B).

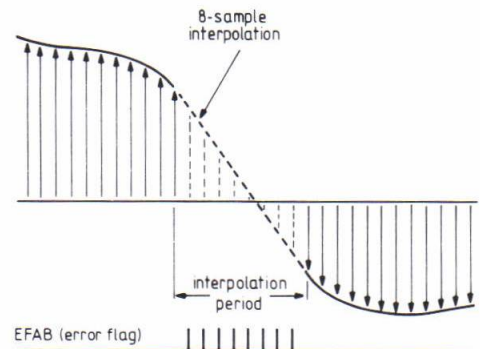


● Check the EFAB signal (Error Flag from Decoder-A to Filter-B) at test point 74 (pin 36)

- Place test disc 5A on the turntable.
- During playback, EFAB pulses should be present at test point 74 for soft braking of the disc and during fast search (F.Forward, F.Reverse).

Note:

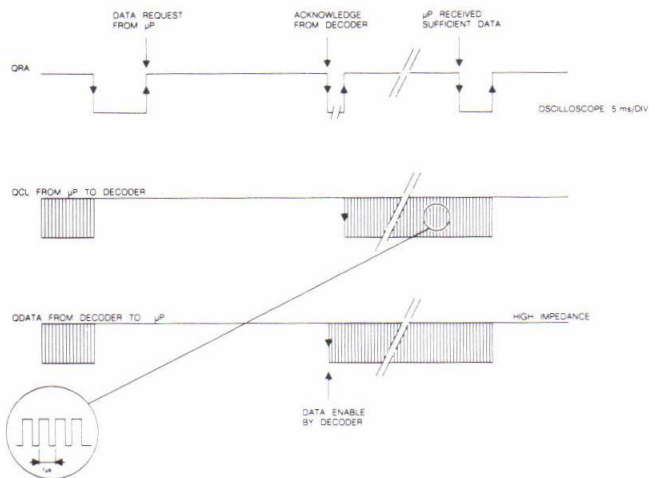
Filter-B IC is capable of interpolating linearly 8 successive EFAB pulses.



● **Check the Q-channel signals**

- Place a disc on the turntable.
- Select one of the following positions: SERVICE POSITION 3 or position PLAY.
- Trigger on the QRA signal (Q-channel Request Acknowledge) test point 75; pin 30.
- Check signals QRA at test point 75 (pin 30) QCL at test point 76 (pin 31) (Q-channel-clock) and their interrelation.
- There should then be activity at test point 77 (pin 29) QDA (Q-channel Data).

Note:
The QRA request is initiated by decoder μ P (QRA "high"). Then Decoder-A answers this request (QRA goes "low"). With the next leading clock pulse (QCL) the QRA signal is rendered "high" again by the decoder μ P.



As soon as the Decoder-A has taken in enough information via QDA, QRA will go low again. That is why the QRA times vary each time.

● **Check the $\overline{\text{SSM}}$ signal (test point 78; pin 33) = Start-Stop turntable motor**

- Motor start pulse when test point 78 is "high" for ≥ 0.2 sec.
- Motor stop pulse when test point 78 is "low" for ≥ 0.2 sec.

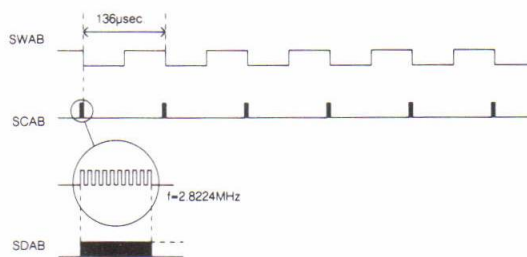
Note:
After the motor start pulse, SWAB information (Subcoding Word clock) will become visible at this point. The period time of that signal is 136 μ sec.

● **Check the subcode clock signals**

- Place a disc on the turntable.
 - Select position PLAY.
 - Trigger the oscilloscope with the SWAB signal at test point 78.
 - Check the following signals:
 - SWAB at test point 78; pin 33
 - SCAB at test point 79; pin 35 (Subcode Clock from Decoder-A to Filter B)
 - SDAB at test point 80; pin 34 (Subcode Data from Decoder-A to Filter B)
- and their interrelations.

Note:

While the burst of 10 clock pulses, appear on SCAB the Q-channel information is transferred on SDAB. Hereafter the P-bit indication follows. The P-bit is "high" between two bursts of 10 clock pulses in case of pause indication and "low" in case of music indication.



● **Check the CRI signal (pin 28; test point 19)**

The CRI signal is "low" in case of track jumping. Player in position SEARCH.

● **Check the DEEM signal (test point 84; pin 32)**

- Place test disc 5 on the turntable.
- During playback of track no. 14 (recorded without PRE-EMPHASIS), the DEEM signal should be "low".
- During playback of track no. 15 (recorded with PRE-EMPHASIS), the DEEM signal should be "high".

IV FILTER-B (Q502)

● **Check the signals between Decoder-A IC and Filter-B IC**

- See sub. "III Decoder-A":
 - * Check the X IN signal (test points 69 and 70)
 - * Check the timing signals meant for Filter B (WSAB, CLAB, DAAB signals; test points 71, 72 and 73).
 - * Check the EFAB signal (test point 74)
 - * Check the subcode clock signals (SWAB, SCAB, SDAB signals; test points 78, 79 and 80).

● **Check the timing signals between Filter-B and DAC IC**

- Place a disc on the turntable.
- Select the position PLAY.
- Trigger the oscilloscope with the WSBD signal (Word Select from Filter B to DAC) test point 85 (pin 18).

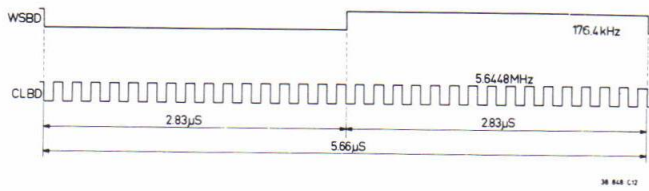
● **Check the following signals:**

- WSBD at test point 85; pin 18
- CLBD at test point 87; pin 16 (Clock signal from Filter-B to DAC) and their interrelation.

If an Audio disc is used, there should be activity at test point 73 (pin 3) DAAB signal (DATA from Decoder - A to Filter-B).

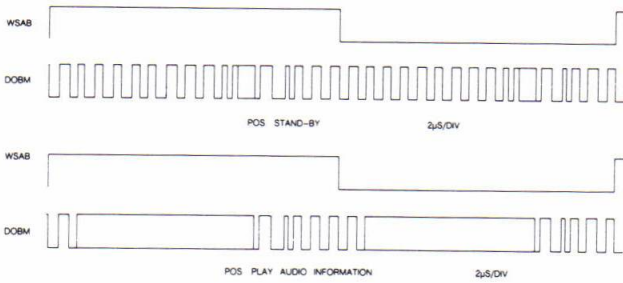
If a disc with Digital Data (CD-ROM) is used, this point is continuously switched "low" by transistor (Q506). Then the ANI signal test point 95 is "HIGH".

In that case the word "data" appears on the display.



● **Check the DOBM signal (Digital Output)**

- Place a disc on the turntable.
- Select the stand-by mode (only mains switch depressed).
- Trigger the oscilloscope with the WSAB signal (test point 71).
- Check the DOBM signal (test point 88; pin 14). An empty audio signal has a fixed pattern. See drawing, "Stand-by".
- Select the PLAY mode. Check the DOBM signal. See drawing "PLAY".



● **In position SEARCH the $\overline{\text{ATSB}}$ signal is "low" test point 89; pin 22 (Attenuation Audio Signal)**

● **Check the $\overline{\text{MUSB}}$ signal test point 90; pin 23 (Soft Mute)**

This signal is "low" in positions:
 PAUSE
 "SKIP \lll " or "SKIP \ggg " when jumping from one track to another.
 During fast SEARCH, when the "FAST" and "SEARCH \lll " or "SEARCH \ggg " keys have been actuated.

V DATA SEPARATION AND DIGITAL PHASE INVERSION SECTION (QD01—QD15)

For the data to DAC, change the DABD (WD01-6) data array and use separated data of L and R.

● **L/R data selection**

L channel data comes first, so it must be delayed by $f_s \times 1/2$ in time to align both channel data. This is the reason why a time delay circuit is added in the L channel data path.

● **Creation of inverted and non-inverted data**

Timings for both the channels are aligned because of only the L channel data delayed. Next, two kinds of data will be prepared. One is a non-inverted data -- original data. The other is an inverted data. To create the inverted data, the data is further delayed by $f_s \times 1/2$ and then inverted.

● **DA conversion and output synthesis**

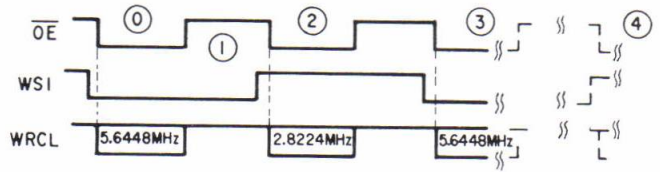
Each L channel inverted/non-inverted data and R channel inverted/non-inverted data is fed to Dual DAC respectively.

● **$\overline{\text{OE}}$ signal**

The $\overline{\text{OE}}$ signal is a signal created by counting down WSBD (WD01-4) signal into 1/2 and delaying it by one clock with CLBD (QD01-pin 6) signal. The time is equivalent to the time for one DABD (WD01-6) signal (a pair of L, R 1).

● **WRCL signal (shift clock of QD04 - QD07)**

The clock is generated when the $\overline{\text{OE}}$ signal is "L". Its frequency is 5.6448 MHz when the WSI (QD03-pin 5) signal is "L" and 2.8224 MHz when the WSI signal is "H".



- The Rch data is stored in QD04 and QD05 and Lch data is stored in QD06 and QD07 under the condition ①. (No data transmission)
- The data is output to QD13 at the rate of 2.8224 MHz BCK; Bit clock (QD02-pin 6) under the condition ②. The QD13 Lch & Rch data outputs are transferred to QD08 and QD09 and to QD10 and QD11, respectively.
- The data of QD08 & QD09 (Lch) and QD10 & QD11 (Rch) are output to the DAC through QD15 (output timing matching) at the timing ③. Simultaneously, the same data but inverted are transferred to QD08 & QD09 (Lch), and QD10 & QD11 (Rch).
- The inverted data entered at the timing 3 is output to DAC at the timing ④.

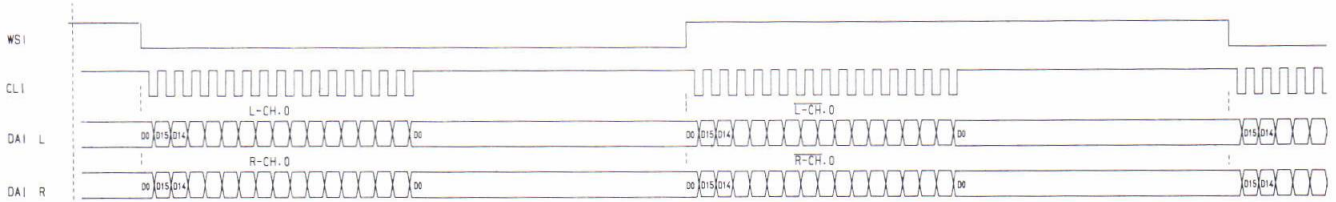
VI DAC IC (QD31, QD61)

Bit Stream Dual Digital Analog Converter

● Features

- I²S data input
 - 3-stage digital filter incorporating F.I.R. filter, linear interpolator and sample and hold
 - 2nd order noise shaper to provide a signal-to-noise ratio of > 90 dB
 - 16-bit resolution from a 1-bit converter, using switched capacitor integrator
 - 3rd order low-pass filter to reduce out-of-band noise
 - –12 dB attenuation, de-emphasis and mute control
 - Low power consumption (typ. 300 mW)
 - Single supply operation (+ 5V)
 - –40 to + 85°C operating temperature range
- **WSI (pin 30) Word Select Input; 44.1 kHz**
 - **CLI (pin 31) Serial bit Clock; 2.8224MHz**
 - **DAI (pin 32) Serial Data Input**

The relations are shown in illustration.

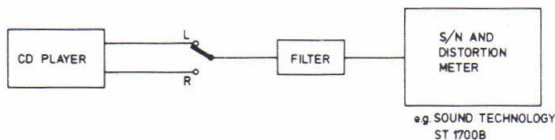


VII DEEM CIRCUIT

● Check DEEM circuit

- Place test disc 5 on the turntable.
- During playback of track no. 14 (recorded without PRE-EMPHASIS) the DEEM signal at test point 84 should be "low".
- During playback of track no. 15 (recorded with PRE-EMPHASIS), the DEEM signal at test point 84 should be "high".

VIII SPECIFICATIONS MEASUREMENT



To measure the specification use can be made of audio test disc 4822 397 30085 use 13th order filter 4822 395 30204 to measure:

- Total harmonic distortion
- Intermodulation distortion
- Signal-to-noise ratio (s/n)

10. ELECTRICAL PARTS LIST

ASSIGNMENT OF COMMON PARTS CODES.

RESISTOR

- R***:** (1) GD05---140, Carbon film fixed resistor, ±5%, 1/4W
R*:** (2) GD05---160, Carbon film fixed resistor, ±5%, 1/6W

① — Resistance value

Examples

① Resistance value

0.1Ω ... 001	10Ω ... 100	1kΩ ... 102	100kΩ ... 104
0.5Ω ... 005	18Ω ... 180	2.7kΩ ... 272	680kΩ ... 684
1Ω ... 010	100Ω ... 101	10kΩ ... 103	1MΩ ... 105
6.8Ω ... 068	390Ω ... 391	22kΩ ... 223	4.7MΩ ... 475

(Note) Please distinguish 1/4W from 1/6W by the shape of parts used actually.

C***: CERAMIC CAP.

- (1) DD1 --- 370, Ceramic condenser
 Disc type
 Temp. coeff. P350 — N1000, 50V
- ① ②
- Capacity value
 Tolerance

Examples

- ① Tolerance (Capacity deviation)
- ±0.25pF ... 0
 - ±0.5pF ... 1
 - ±5% ... 5

* Tolerance of COMMON PARTS handled here are as follows.

0.5pF ~ 5pF ... ±0.25pF
6pF ~ 10pF ... ±0.5pF
12pF ~ 560pF ... ±5pF
② Capacity value
0.5pF ... 005 3pF ... 030 100pF ... 101
1pF ... 010 10pF ... 100 220pF ... 221
1.5pF ... 015 47pF ... 470 560pF ... 561

C***: CERAMIC CAP.

- (1) DK16---300, High dielectric constant ceramic condenser
 Disc type
 Temp. chara. 2B4, 50V
- ①
- Capacity value

Examples

② Capacity value

100pF ... 101	1000pF ... 102	10000pF ... 103
470pF ... 471	2200pF ... 222	

C***: ELECTROLY CAP. (⏏), FILM CAP. (⏏)

- (1) EA---10, Electrolytic condenser
 One-way lead type, Tolerance ±20%
- ① ②
- Dielectric strength
 Capacity value

Examples

① Capacity value

0.1μF ... 104	4.7μF ... 475	100μF ... 107
0.33μF ... 334	10μF ... 106	330μF ... 337
1μF ... 105	22μF ... 226	1100μF ... 108
		2200μF ... 228

- ② Working voltage
- | | |
|--------------|-------------|
| 6.3V ... 006 | 25V ... 025 |
| 10V ... 010 | 35V ... 035 |
| 16V ... 016 | 50V ... 050 |

- (2) DF15---350, Plastic film condenser
 One-way type, Mylar ±5% 50V
- ①
- Capacity value

Examples

① Capacity value

0.001μF (1000pF) ... 102	0.1μF ... 104
0.0018μF ... 182	0.56μF ... 564
0.01μF ... 103	1μF ... 105
0.015μF ... 153	

REF. DESIG.	PART NO.	DESCRIPTION
		PB16-BALANCE OUT CIRCUIT BOARD
		PB16-CAPACITORS
C701		
}	4822 124 90386	ELECT 10 μ F 25V
C704		
C705	4822 121 51144	FILM 1000PF ±2%
C706	4822 121 51144	FILM 1000PF ±2%
C707	4822 124 22238	ELECT 100 μ F 25V
C708	4822 124 22238	ELECT 100 μ F 25V
C717	4822 121 51209	FILM 0.015 μ F ±2%
C718	4822 121 51209	FILM 0.015 μ F ±2%
C719	4822 123 30093	MICA 5PF ±0.5PF
C720	4822 123 30093	MICA 5PF ±0.5PF
C731		
}	4822 124 22572	ELECT 100 μ F 63V
C734		
C737	4822 124 22736	ELECT 1000 μ F 25V
C738	4822 124 22736	ELECT 1000 μ F 25V
C798	4822 122 40491	CERAMIC 0.022 μ F +80% -20%
CT01	4822 124 41539	ELECT 47 μ F 16V
CT02	4822 122 40491	CERAMIC 0.022 μ F +80% -20%
CT06	4822 122 40491	CERAMIC 0.022 μ F +80% -20%
CT07	4822 122 40617	CERAMIC 0.1 μ F +80% -20%
		PB16-RESISTORS
R701	4822 116 53387	5.62K Ω ±2% 1/4W
R702	4822 116 53387	5.62K Ω ±2% 1/4W
R703	4822 050 24642	4.64K Ω ±2% 1/4W
R704	4822 050 24642	4.64K Ω ±2% 1/4W
R705	4822 116 53387	5.62K Ω ±2% 1/4W
R706	4822 116 53387	5.62K Ω ±2% 1/4W
R707	4822 116 82588	15.4K Ω ±2% 1/4W
R708	4822 116 82588	15.4K Ω ±2% 1/4W
R709	4822 050 21002	1K Ω ±2% 1/4W
R710	4822 050 21002	1K Ω ±2% 1/4W
R711		
}	4822 116 53387	5.62K Ω ±2% 1/4W
R714		
R715		
}	4822 050 25621	562 Ω ±2% 1/4W
R718		
R719	4822 116 53784	68.1K Ω ±2% 1/4W
R720	4822 116 53784	68.1K Ω ±2% 1/4W
▲ R731		
}	4822 111 90731	47 Ω ±2% 1/4W
▲ R734		
▲ R737	4822 116 53387	5.62K Ω ±2% 1/4W
▲ R738	4822 116 53387	5.62K Ω ±2% 1/4W
		PB16-SEMICONDUCTORS
D703	4822 130 33305	DIODE 1SS176, ETC.
Q701		
}	4822 209 70226	I C NJM5534D
Q704		
QT01	4822 209 72503	I C 74HC04
QT02	4822 209 73951	I C PST523D

REF. DESIG.	PART NO.	DESCRIPTION
PB16-MISCELLANEOUS		
J071	4822 264 10226	PLUG (CANON 3P XLR)
J072	4822 264 10226	PLUG (CANON 3P XLR)
J701	4822 265 10079	PLUG, 9P
J703	4822 265 30473	PLUG, 6P
JT01	4822 265 30482	PLUG, 4P
JT02	4822 265 20354	TERMINAL, 1P RCA
JT04	4822 267 31219	JACK, OPT CONNECTOR TOTX174
L701	4822 148 80787	OUTPUT TRANSFORMER
L702	4822 148 80787	OUTPUT TRANSFORMER
L703	4822 280 20448	RELAY, DC9V
L705	4822 158 60605	FERRITE CORE
L708		
LT01	4822 158 60605	FERRITE CORE
LT02	4822 142 60388	PULSE TRANSFORMER
W071	4822 321 60772	CONNECTIVE CORD, 3P
PD16-DAC CIRCUIT BOARD		
PD16-CAPACITORS		
CD01	4822 124 41539	ELECT 47 μ F 16V
CD02	4822 122 33136	CERAMIC 0.022 μ F \pm 10%
CD05		
CD07	4822 122 33136	CERAMIC 0.022 μ F \pm 10%
CD08	4822 122 33136	CERAMIC 0.022 μ F \pm 10%
CD10	4822 122 33136	CERAMIC 0.022 μ F \pm 10%
CD21	4822 124 22238	ELECT 220 μ F 10V
CD22	4822 122 32669	CERAMIC 47000PF +80% -20%
CD24	4822 124 22238	ELECT 220 μ F 10V
CD25	4822 122 32669	CERAMIC 47000PF +80% -20%
CD26	4822 124 22238	ELECT 220 μ F 10V
CD27	4822 122 32669	CERAMIC 47000PF +80% -20%
CD28	4822 124 22238	ELECT 220 μ F 10V
CD29	4822 122 32669	CERAMIC 47000PF +80% -20%
CD32	4822 122 32686	CERAMIC 100PF \pm 5%
CD33	4822 122 32686	CERAMIC 100PF \pm 5%
CD36	4822 121 51144	FILM 1000PF \pm 2%
CD37	4822 121 51144	FILM 1000PF \pm 2%
CD38	4822 122 32921	CERAMIC 150PF \pm 5%
CD39	4822 122 32921	CERAMIC 150PF \pm 5%
CD40	4822 121 43734	MICA 330PF \pm 5%, CHIP
CD41	4822 121 43734	MICA 330PF \pm 5%, CHIP
CD44	4822 124 90386	ELECT 10 μ F 25V
CD45	4822 124 90386	ELECT 10 μ F 25V
CD50	4822 124 22238	ELECT 100 μ F 25V
CD51	4822 122 32669	CERAMIC 47000PF +80% -20%
CD52	4822 124 22238	ELECT 100 μ F 25V
CD53	4822 122 32669	CERAMIC 47000PF +80% -20%
CD62	4822 124 22238	ELECT 220 μ F 10V
CD63	4822 122 32669	CERAMIC 0.047 μ F +80% -20%
CD64	4822 124 22238	ELECT 220 μ F 10V
CD65	4822 122 32669	CERAMIC 0.047 μ F +80% -20%
CD66	4822 124 22238	ELECT 220 μ F 10V
CD67	4822 122 32669	CERAMIC 0.047 μ F +80% -20%
CD68	4822 124 22238	ELECT 220 μ F 10V
CD69	4822 122 32669	CERAMIC 0.047 μ F +80% -20%
CD72	4822 122 32686	CERAMIC 100PF \pm 5%
CD73	4822 122 32686	CERAMIC 100PF \pm 5%
CD76	4822 121 51144	FILM 1000PF \pm 2%
CD77	4822 121 51144	FILM 1000PF \pm 2%
CD78	4822 122 32921	CERAMIC 150PF \pm 5%

REF. DESIG.	PART NO.	DESCRIPTION
CD79	4822 122 32921	CERAMIC 150PF \pm 5%
CD80	4822 121 43734	MICA 330PF \pm 5%, CHIP
CD81	4822 121 43734	MICA 330PF \pm 5%, CHIP
CD82	4822 124 90386	ELECT 10 μ F 25V
CD83	4822 124 90386	ELECT 10 μ F 25V
CD90	4822 124 22238	ELECT 100 μ F 25V
CD91	4822 122 32669	CERAMIC 0.047 μ F +80% -20%
CD92	4822 124 22238	ELECT 100 μ F 25V
CD93	4822 122 32669	CERAMIC 0.047 μ F +80% -20%
PD16-RESISTORS		
RD02	4822 116 60446	3.3 Ω \pm 5% 1/4WFUSE [E, W]
RD02		1.5 Ω \pm 5% 1/4W [U]
RD04	4822 116 60446	3.3 Ω \pm 5% 1/4WFUSE [E, W]
RD04		1.5 Ω \pm 5% 1/4W [U]
RD05	4822 116 60446	3.3 Ω \pm 5% 1/4WFUSE [E, W]
RD05		1.5 Ω \pm 5% 1/4W [U]
RD21	4822 111 90895	10K Ω \pm 5% 1/10W, CHIP
RD22	4822 111 90895	10K Ω \pm 5% 1/10W, CHIP
RD28	4822 116 82573	22K Ω \pm 5% 1/10W, CHIP
RD29	4822 116 82573	22K Ω \pm 5% 1/10W, CHIP
RD30	4822 111 90891	9.1K Ω \pm 1% 1/10W, CHIP
RD31	4822 111 90891	9.1K Ω \pm 1% 1/10W, CHIP
RD32	4822 111 91364	3.9K Ω \pm 1% 1/10W, CHIP
RD35		
RD36	4822 111 91139	6.8K Ω \pm 5% 1/10W, CHIP
RD37	4822 111 91139	6.8K Ω \pm 5% 1/10W, CHIP
RD40	4822 111 90893	100 Ω \pm 5% 1/10W, CHIP
RD41	4822 111 90893	100 Ω \pm 5% 1/10W, CHIP
RD42	4822 116 82589	3.3M Ω \pm 5% 1/10W, CHIP
RD43	4822 116 82589	3.3M Ω \pm 5% 1/10W, CHIP
RD52	4822 111 90895	10K Ω \pm 5% 1/10W, CHIP
RD62	4822 116 60446	3.3 Ω \pm 5% 1/4WFUSE [E, W]
RD62		1.5 Ω \pm 5% 1/4W [U]
RD64	4822 116 60446	3.3 Ω \pm 5% 1/4WFUSE [E, W]
RD64		1.5 Ω \pm 5% 1/4W [U]
RD65	4822 116 60446	3.3 Ω \pm 5% 1/4WFUSE [E, W]
RD65		1.5 Ω \pm 5% 1/4W [U]
RD68	4822 116 82573	22K Ω \pm 5% 1/10W, CHIP
RD69	4822 116 82573	22K Ω \pm 5% 1/10W, CHIP
RD70	4822 111 90891	9.1K Ω \pm 1% 1/10W, CHIP
RD71	4822 111 90891	9.1K Ω \pm 1% 1/10W, CHIP
RD72	4822 111 91364	3.9K Ω \pm 1% 1/10W, CHIP
RD75		
RD76	4822 111 91139	6.8K Ω \pm 5% 1/10W, CHIP
RD77	4822 111 91139	6.8K Ω \pm 5% 1/10W, CHIP
RD80	4822 111 90893	100 Ω \pm 5% 1/10W, CHIP
RD81	4822 111 90893	100 Ω \pm 5% 1/10W, CHIP
RD82	4822 116 82589	3.3M Ω \pm 5% 1/10W, CHIP
RD83	4822 116 82589	3.3M Ω \pm 5% 1/10W, CHIP
PD16-SEMICONDUCTORS		
QD01	4822 209 82377	I C 74HC00
QD02	4822 209 61494	I C 74HC74
QD03	4822 209 61494	I C 74HC74
QD04	4822 209 62764	I C 74HC164
QD11		
QD12	4822 209 61494	I C 74HC74
QD13	4822 209 62765	I C 74HC258
QD15	4822 209 61494	I C 74HC74
QD31	4822 209 62758	I C SAA7321
QD61	4822 209 62758	I C SAA7321
QD63	4822 209 73951	I C PST523D

REF. DESIG.	PART NO.	DESCRIPTION
PD16-MISCELLANEOUS		
LD21	4822 157 62546	CHOKE COIL, 4.7 μ H
LD22	4822 157 62547	CHOKE COIL, 820 μ H
LD23	4822 157 62547	CHOKE COIL, 820 μ H
LD61	4822 157 62546	CHOKE COIL, 4.7 μ H
LD62	4822 157 62547	CHOKE COIL, 820 μ H
LD63	4822 157 62547	CHOKE COIL, 820 μ H
JD02	4822 265 10079	PLUG, 9P
PP16-POWER/MIXAMP CIRCUIT BOARD		
PP16-CAPACITORS		
C605	4822 123 30093	MICA 5PF \pm 0.5PF
C606	4822 123 30093	MICA 5PF \pm 0.5PF
C607	4822 124 22572	ELECT 100 μ F 63V
C610		
C611	4822 124 22238	ELECT 100 μ F 25V
C614		
C617	4822 124 23398	ELECT 220 μ F 10V
C618	4822 124 23398	ELECT 220 μ F 10V
C621	4822 124 23398	ELECT 220 μ F 10V
C622	4822 124 23398	ELECT 220 μ F 10V
C830	4822 122 40491	CERAMIC 0.022 μ F +80% -20%
C834	4822 124 90367	ELECT 2200 μ F 25V
C835	4822 124 90367	ELECT 2200 μ F 25V
C836	4822 124 90364	ELECT 220 μ F 16V
C837	4822 124 90364	ELECT 220 μ F 16V
C840	4822 122 40491	CERAMIC 0.022 μ F +80% -20%
C842	4822 124 22243	ELECT 6800 μ F 16V
C845	4822 124 23403	ELECT 6800 μ F 6.3V
C853	4822 124 42037	ELECT 6800 μ F 35V
C854	4822 124 42037	ELECT 6800 μ F 35V
C855	4822 124 23364	ELECT 47 μ F 50V
C856	4822 124 23364	ELECT 47 μ F 50V
C857	4822 124 22734	ELECT 470 μ F 25V
C858	4822 124 22734	ELECT 470 μ F 25V
C862	4822 124 22722	ELECT 1000 μ F 16V
C863	4822 124 23363	ELECT 220 μ F 6.3V
CN01	4822 124 22274	ELECT 4.7 μ F 50V
PP16-RESISTORS		
R601	4822 050 24642	4.64K Ω \pm 2% 1/4W
R604		
R605	4822 116 53387	5.62K Ω \pm 2% 1/4W
R608		
R609	4822 050 24642	4.64K Ω \pm 2% 1/4W
R610	4822 050 24642	4.64K Ω \pm 2% 1/4W
R613	4822 050 21001	100 Ω \pm 2% 1/4W
R614	4822 050 21001	100 Ω \pm 2% 1/4W
R615	4822 050 22153	21.5K Ω \pm 2% 1/4W
R616	4822 050 22153	21.5K Ω \pm 2% 1/4W
R617	4822 050 21003	10K Ω \pm 2% 1/4W
R618	4822 050 21003	10K Ω \pm 2% 1/4W
R621	4822 111 90731	47 Ω \pm 2% 1/4W, FUSE
R628		
R631	4822 116 53791	1.54K Ω \pm 2% 1/4W
R632	4822 116 53791	1.54K Ω \pm 2% 1/4W
R633	4822 050 21001	100 Ω \pm 2% 1/4W
R634	4822 050 21001	100 Ω \pm 2% 1/4W
R801	4822 116 60346	2.2K Ω \pm 5% 1W
R802	4822 116 60346	2.2K Ω \pm 5% 1W

REF. DESIG.	PART NO.	DESCRIPTION
R803	4822 116 53297	1.78K Ω \pm 2% 1/4W
R806		
R807	4822 050 21212	1.21K Ω \pm 2% 1/4W
R808	4822 050 21212	1.21K Ω \pm 2% 1/4W
R809	4822 116 53297	1.78K Ω \pm 2% 1/4W
R810	4822 116 53297	1.78K Ω \pm 2% 1/4W
R811	4822 050 21212	1.21K Ω \pm 2% 1/4W
R812	4822 050 21212	1.21K Ω \pm 2% 1/4W
R813	4822 111 90967	4.7 Ω \pm 5% 1/4W [E, W]
R814	4822 111 90967	4.7 Ω \pm 5% 1/4W [E, W]
R861	4822 050 25621	562 Ω \pm 2% 1/4W
R863	4822 116 53297	1.78K Ω \pm 2% 1/4W
R864	4822 116 53758	1.62K Ω \pm 2% 1/4W
PP16-SEMICONDUCTORS		
Q601	4822 209 70226	I C NJM5534D
Q604		
QN01	4822 209 83312	I C TA7317P
D602	4822 130 33305	DIODE 1SS176, ETC.
▲ D831	4822 130 80907	DIODE S2VB20
▲ D841	4822 130 80907	DIODE S2VB20
▲ D851	4822 130 33074	DIODE 30DF-2
▲ D854		
D855	4822 130 33664	ZENER DIODE HZ6L (3) 6.2V
D856	4822 130 33664	ZENER DIODE HZ6L (3) 6.2V
D861	4822 130 33305	DIODE 1SS176, ETC.
▲ Q851	4822 130 43023	TRANSISTOR 2SA1306 (O, Y)
▲ Q852	4822 130 43311	TRANSISTOR 2SC3298 (O, Y)
▲ Q853	4822 130 60107	TRANSISTOR 2SA1048 (Y, GR)
▲ Q854	4822 130 60839	TRANSISTOR 2SC2458 (Y, GR)
Q855	4822 130 60107	TRANSISTOR 2SC1048 (Y, GR)
Q856	4822 130 60839	TRANSISTOR 2SC2458 (Y, GR)
Q861	4822 130 43311	TRANSISTOR 2C3298 (O, Y)
Q862	4822 130 60839	TRANSISTOR 2SC2458 (Y, GR)
Q863	4822 209 62759	I C NJM431
PP16-MISCELLANEOUS		
▲ F831	4822 253 20168	FUSE, T800MA [E, W]
▲ F831		FUSE, 1A [U]
▲ F832	4822 253 30201	FUSE, T800MA [E, W]
▲ F832		FUSE, 1A [U]
▲ F841	4822 253 20145	FUSE, T1.25A [E, W]
▲ F841	4822 253 40196	FUSE, 1.6A [U]
▲ F851	4822 253 20168	FUSE, T800MA [E, W]
▲ F851		FUSE, 1A [U]
▲ F852	4822 253 20168	FUSE, T800MA [E, W]
▲ F852		FUSE, 1A [U]
J602	4822 267 30955	TERMINAL, 2P RCA
L602	4822 280 20448	RELAY, DC9V
L605	4822 158 60605	FERRITE CORE
L606	4822 158 60605	FERRITE CORE
PP26-REG. CIRCUIT BOARD		
PP26-SEMI CONDUCTORS		
D842	4822 130 33305	DIODE 1SS176, ETC.
▲ Q831	4822 209 62762	I C NJM7909FA
▲ Q832	4822 209 62761	I C NJM7809FA
▲ Q841	4822 209 71903	I C NJM7805FA

REF. DESIG.	PART NO.	DESCRIPTION
		PS26-POWER SWITCH CIRCUIT BOARD
		PS26-CAPACITOR
CH01	4822 121 43733	FILM 0.068 μ F \pm 20%
GH02	4822 121 43732	FILM 0.01 μ F \pm 20%
		PS26-MISCELLANEOUS
LH01	4822 152 20637	NOISE FILTER, CHOKE
SH02	4822 276 11141	PUSH SWITCH, POWER
		PU16-CONTROL/DECODER CIRCUIT BOARD
		PU16-CAPACITORS
C501	4822 122 32686	CERAMIC 100PF \pm 5%
C504	4822 124 22274	ELECT 4.7 μ F 50V
C506	4822 122 33132	CERAMIC 22PF \pm 5%
C507	4822 126 11058	CERAMIC 82PF \pm 5%
C508	4822 122 33136	CERAMIC 0.022 μ F \pm 10%
C509	4822 124 90352	ELECT 10 μ F 16V
C510	4822 122 33136	CERAMIC 0.022 μ F \pm 10%
C513	4822 122 32669	CERAMIC 0.047 μ F +80% -20%
C516	4822 122 33677	CERAMIC 27PF \pm 5%
C517	4822 122 33677	CERAMIC 27PF \pm 5%
C520	4822 124 90371	ELECT 470 μ F 10V
C531	4822 122 32669	CERAMIC 0.047 μ F +80% -20%
C532	4822 122 32669	CERAMIC 0.047 μ F +80% -20%
CF03	4822 124 22274	ELECT 4.7 μ F 50V
CF04	4822 124 41539	ELECT 47 μ F 16V
CF05	4822 122 33136	CERAMIC 0.022 μ F \pm 10%
CF06	4822 122 33136	CERAMIC 0.022 μ F \pm 10%
CF07	4822 124 41539	ELECT 47 μ F 16V
CF08	4822 122 33136	CERAMIC 0.022 μ F \pm 10%
CF09	4822 124 41539	ELECT 47 μ F 16V
CF10	4822 122 33136	CERAMIC 0.022 μ F \pm 10%
CF13	4822 124 41539	ELECT 47 μ F 16V
CF14	4822 122 33136	CERAMIC 0.022 μ F \pm 10%
CF15	4822 124 90371	ELECT 470 μ F 10V
CF16	4822 122 33136	CERAMIC 0.022 μ F \pm 10%
CF17	4822 122 33689	CERAMIC 0.01 μ F \pm 10%
CF18	4822 122 33689	CERAMIC 0.01 μ F \pm 10%
CF19	4822 122 32669	CERAMIC 0.047 μ F +80% -20%
CF50	4822 122 32669	CERAMIC 0.047 μ F +80% -20%
CM01	4822 124 22274	ELECT 4.7 μ F 50V
CM04	4822 122 33689	CERAMIC 0.01 μ F \pm 10%
CM05	4822 122 33689	CERAMIC 0.01 μ F \pm 10%
		PU16-RESISTORS
R501	4822 111 90906	2.2K Ω \pm 5% 1/10W, CHIP
R502	4822 116 82573	22K Ω \pm 1% 1/10W, CHIP
R503	4822 111 91075	1.2K Ω \pm 5% 1/10W, CHIP
R504	4822 116 82591	39 Ω \pm 5% 1/10W, CHIP
R505	4822 111 90918	4.7K Ω \pm 5% 1/10W, CHIP
R506	4822 111 90895	10K Ω \pm 5% 1/10W, CHIP
R508	4822 111 91372	820 Ω \pm 5% 1/10W, CHIP
R509	4822 111 90901	150K Ω \pm 5% 1/10W, CHIP
R510	4822 111 90901	150K Ω \pm 5% 1/10W, CHIP
R511	4822 111 90892	0 Ω \pm 5% 1/10W, CHIP
R515	4822 111 90918	4.7K Ω \pm 5% 1/10W, CHIP
R520	4822 111 90967	4.7 Ω \pm 5% 1/4W, FUSE
RF03	4822 111 90895	10K Ω \pm 5% 1/10W, CHIP
RF04	4822 116 82573	22K Ω \pm 1% 1/10W, CHIP
RF05	4822 111 90903	18K Ω \pm 5% 1/10W, CHIP

REF. DESIG.	PART NO.	DESCRIPTION
RF06	4822 111 90895	10K Ω \pm 5% 1/10W, CHIP
RF12		
RF13	4822 111 90918	4.7K Ω \pm 5% 1/10W, CHIP
RF15	4822 111 90897	1M Ω \pm 5% 1/10W, CHIP
RF22	4822 111 90967	4.7 Ω \pm 5% 1/4W, FUSE
RF23	4822 111 90895	10K Ω \pm 5% 1/10W, CHIP
RF25		
RF26	4822 111 90896	100K Ω \pm 5% 1/10W, CHIP
RF27	4822 116 82573	22K Ω \pm 1% 1/10W, CHIP
RF29	4822 111 90895	10K Ω \pm 5% 1/10W, CHIP
RF30	4822 111 90895	10K Ω \pm 5% 1/10W, CHIP
RF41		
RF48	4822 111 90895	10K Ω \pm 5% 1/10W, CHIP
RF49	4822 111 90906	2.2K Ω \pm 5% 1/10W, CHIP
RF99	4822 111 90895	10K Ω \pm 5% 1/10W, CHIP
RM01	4822 111 90919	47K Ω \pm 5% 1/10W, CHIP
RM02	4822 111 90918	4.7K Ω \pm 5% 1/10W, CHIP
RM03	4822 111 90918	4.7K Ω \pm 5% 1/10W, CHIP
RM06		
	4822 111 90918	4.7K Ω \pm 5% 1/10W, CHIP
RM08		
RM11	4822 111 90918	4.7K Ω \pm 5% 1/10W, CHIP
		PU16-SEMICONDUCTORS
DF02	4822 130 32868	DIODE MA153, CHIP
DM02	4822 130 32635	DIODE MA-151K, CHIP
DM03	4822 130 32866	DIODE MA151WA, CHIP
DM05	4822 130 32635	DIODE MA-151K, CHIP
DM06		
	4822 130 32866	DIODE MA151WA, CHIP
DM08		
Q501	4822 209 71001	I C SAA7210P
Q502	4822 209 72545	I C SAA7220P/B
Q503	4822 209 73952	I C MB81416C-15/MN4264P-15
Q504	4822 130 61438	TRANSISTOR 2SA1005 (L, K)
Q505	4822 130 90323	TRANSISTOR, DIGITAL DTC114TK
Q506	4822 130 90323	TRANSISTOR, DIGITAL DTC114TK
QF01	4822 209 62768	MICROPROCESSOR MC68HC11A0P
QF02	4822 209 62756	I C MC68HC24
QF04	4822 209 62757	I C M27128A-2F1
QF05	4822 209 62766	I C 74HC373
QF06	4822 209 51273	I C MSM2816A
QF08		
	4822 209 82377	I C 74HC00
QF10		
QF11	4822 209 73951	I C PST523D
QF12	4822 209 61494	I C 74HC74
QF13	4822 130 61436	TRANSISTOR, DIGITAL DTA114YK
QF14	4822 130 90449	TRANSISTOR, DIGITAL DTC144EK
QF16	4822 130 61436	TRANSISTOR, DIGITAL DTA114YK
QM01	4822 209 83803	I C LB1645N
QM02	4822 209 83803	I C LB1645N
QM03	4822 209 82377	I C 74HC00
QM04	4822 130 90449	TRANSISTOR, DIGITAL DTC-144
QM05		
	4822 130 60941	TRANSISTOR, DIGITAL DTA114EK
QM07		
QM08	4822 130 90449	TRANSISTOR, DIGITAL DTC-144
QM09	4822 130 90449	TRANSISTOR, DIGITAL DTC-144

REF. DESIG.	PART NO.	DESCRIPTION
PU16-MISCELLANEOUS		
J501	4822 265 40564	PLUG, 8P
J502		PLUG, 2P
J503	4822 267 40793	PLUG, 5P
J504	4822 265 30482	PLUG, 4P
JF01	4822 265 10216	PLUG, 10P
JF02	4822 265 40772	PLUG, 14P
JF04	4822 265 30482	PLUG, 4P
JM01		PLUG, 12P
L501	4822 152 20647	CHOKO COIL 2.2 μ H
X501	4822 242 72395	CRYSTAL 11.2896MHZ
XF01	4822 242 73696	SERARIC VIBRATOR, 3P, 8.0MHZ
PV16-SERVO CIRCUIT BOARD		
PV16-CAPACITORS		
C101	4822 121 42327	FILM 470PF \pm 5%
C103	4822 122 40491	CERAMIC 0.022 μ F +80% -20%
C110	4822 124 41539	ELECT 47 μ F 16V
C112	5322 122 31626	CERAMIC 100PF \pm 5%
C113	4822 122 40491	CERAMIC 0.022 μ F +80% -20%
C114	4822 122 40491	CERAMIC 0.022 μ F +80% -20%
C128	4822 122 40491	CERAMIC 0.022 μ F +80% -20%
C129	4822 121 43744	FILM 3600PF \pm 5%
C130	4822 121 43744	FILM 3600PF \pm 5%
C132	4822 122 40491	CERAMIC 0.022 μ F +80% -20%
C133	4822 124 41539	ELECT 47 μ F 16V
C134	4822 124 41539	ELECT 47 μ F 16V
C135	4822 122 40491	CERAMIC 0.022 μ F +80% -20%
C136	4822 122 40491	CERAMIC 0.022 μ F +80% -20%
C137	4822 124 41539	ELECT 47 μ F 16V
C138	4822 124 42033	ELECT 1.5 μ F 50V BI-POLA
C145	4822 124 41539	ELECT 47 μ F 16V
C146	4822 124 41539	ELECT 47 μ F 16V
C147	4822 122 40491	CERAMIC 0.022 μ F +80% -20%
C148	4822 122 40491	CERAMIC 0.022 μ F +80% -20%
C150	4822 124 41539	ELECT 47 μ F 16V
PV16-RESISTORS		
R134	4822 100 11373	4.7K Ω , TRIMMING
R136	4822 100 11352	22K Ω , TRIMMING
R164		
1	4822 111 90967	4.7 Ω \pm 5% 1/4W, FUSE
R166		
PV16-SEMICONDUCTORS		
D131	4822 130 33305	DIODE 1SS176, ETC.
D132	4822 130 80272	ZENER DIODE 7.5V 04AZ7.5, ETC.
D133	4822 130 80272	ZENER DIODE 7.5V 04AZ7.5, ETC.
D141	4822 130 33305	DIODE 1SS176, ETC.
D142	4822 130 33305	DIODE 1SS176, ETC.
Q101	4822 209 62754	I C TDA5708
Q102	4822 130 61441	TRANSISTOR 2SD1862 (Q, R)
Q103	4822 209 83203	I C TDA5709
Q104	4822 130 60839	TRANSISTOR 2SC2458 (Y, GR)
Q105	4822 130 60107	TRANSISTOR 2SA1048 (Y, GR)
Q106	4822 209 62755	I C TCA0372
Q108	4822 209 83825	I C NJM39L05
Q141	4822 209 83627	I C NJM4560D

REF. DESIG.	PART NO.	DESCRIPTION
PY16-DISPLAY CIRCUIT BOARD		
PY16-CAPACITORS		
CY01	4822 122 40617	CERAMIC 0.1 μ F +80% -20%
CY02	4822 124 90354	ELECT 100 μ F 16V
CY04	4822 124 22571	ELECT 10 μ F 50V
CY05	5322 122 31626	CERAMIC 100PF \pm 5%
CY06	5322 122 31626	CERAMIC 100PF \pm 5%
CY07	4822 124 22274	ELECT 4.7 μ F 50V
CY11	4822 124 90354	ELECT 100 μ F 16V
CY12	4822 122 40491	CERAMIC 0.022 μ F +80% -20%
CY13	4822 122 40491	CERAMI 0.022 μ F +80% -20%
CY41	4822 122 40491	CERAMIC 0.022 μ F +80% -20%
CY51	4822 124 41539	ELECT 47 μ F 16V
CY52	4822 124 41539	ELECT 47 μ F 16V
CY61	4822 122 40491	CERAMIC 0.022 μ F +80% -20%
CY62	4822 124 41536	ELECT 100 μ F 35V
CY63	4822 124 41536	ELECT 100 μ F 35V
CY73	4822 122 40491	CERAMIC 0.022 μ F +80% -20%
PY16-SEMICONDUCTORS		
DY01		
1	4822 130 33305	DIODE 1SS176, ETC.
DY05		
DY08	4822 130 33305	DIODE 1SS176, ETC.
DY09	4822 130 80319	ZENER DIODE 9.1V 04AZ9.1, ETC.
DY41		
1	4822 130 80326	L. E. D. LT3D8B
DY44		
DY51		
1	4822 130 33305	DIODE 1SS176, ETC.
DY53		
DY61	4822 130 80839	DIODE S5688G
DY62	4822 130 80839	DIODE S5688G
QY01	4822 209 62769	MICROPROCESSOR UPD7537A
QY05	4822 209 62763	I C TC74HC164BP
QY06		
1	4822 130 61186	TRANSISTOR, DIGITAL DTA114TS
QY13		
QY41	4822 209 62767	I C 74HC595
QY42		
1	4822 130 61189	TRANSISTOR, DIGITAL DTC114TS
QY45		
QY51	4822 130 42715	TRANSISTOR 2SA608SP, ETC.
QY52	4822 130 61189	TRANSISTOR, DIGITAL DTC114TS
QY53	4822 130 61186	TRANSISTOR, DIGITAL DTA114TS
QY54	4822 130 61441	TRANSISTOR 2SD1862 (Q, R)
PY16-MISCELLANEOUS		
JY01	4822 265 10216	PLUG, 10P
JY02	4822 265 30482	PLUG, 4P
SY01		
1	4822 276 12455	PUSH SWITCH
SY09		
VY01	4822 130 90884	DISPLAY UNIT, 5-BT-83GK
VY02	4822 130 90884	DISPLAY UNIT, 5-BT-83GK
XY01	4822 242 73695	SERAMIC VIBRATOR, 590kHz
ZY01	4822 130 82197	PHOTO UNIT, IR RECEIVER

NOTE ON SAFETY:

Symbol **▲** Fire or electrical shock hazard. Only original parts should be used to replace any part marked with symbol **▲**. Any other component substitution (other than original type), may increase risk of fire or electrical shock hazard.